

INAx181 Bidirectional, Low- and High-Side Voltage Output, Current-Sense Amplifiers

1 Features

- Common-Mode Range (V_{CM}): -0.2 V to $+26$ V
- High Bandwidth: 350 kHz (A1 Devices)
- Offset Voltage:
 - ± 150 μ V (Max) at $V_{CM} = 0$ V
 - ± 500 μ V (Max) at $V_{CM} = 12$ V
- Output Slew Rate: 2 V/ μ s
- Bidirectional Current-Sensing Capability
- Accuracy:
 - $\pm 1\%$ Gain Error (Max)
 - 1- μ V/ $^{\circ}$ C Offset Drift (Max)
- Gain Options:
 - 20 V/V (A1 Devices)
 - 50 V/V (A2 Devices)
 - 100 V/V (A3 Devices)
 - 200 V/V (A4 Devices)
- Quiescent Current: 260 μ A Max (INA181)

2 Applications

- Motor Control
- Battery Monitoring
- Power Management
- Lighting Control
- Overcurrent Detection
- Solar Inverters

3 Description

The INA181, INA2181, and INA4181 (INAx181) current sense amplifiers are designed for cost-optimized applications. These devices are part of a family of bidirectional, current-sense amplifiers (also called current-shunt monitors) that sense voltage drops across current-sense resistors at common-mode voltages from -0.2 V to $+26$ V, independent of the supply voltage. The INAx181 family integrates a matched resistor gain network in four, fixed-gain device options: 20 V/V, 50 V/V, 100 V/V, or 200 V/V. This matched gain resistor network minimizes gain error and reduces the temperature drift.

These devices operate from a single 2.7-V to 5.5-V power supply. The single-channel INA181 draws a maximum supply current of 260 μ A; whereas, the dual-channel INA2181 draws a maximum supply current of 450 μ A, and the quad-channel INA4181 draws a maximum supply current of 900 μ A.

The INA181 is available in a 6-pin, SOT-23 package, the INA2181 is available in an 10-pin VSSOP package, and the INA4181 is available in a 20-pin TSSOP package. All device options are specified over the extended operating temperature range of -40° C to $+125^{\circ}$ C.

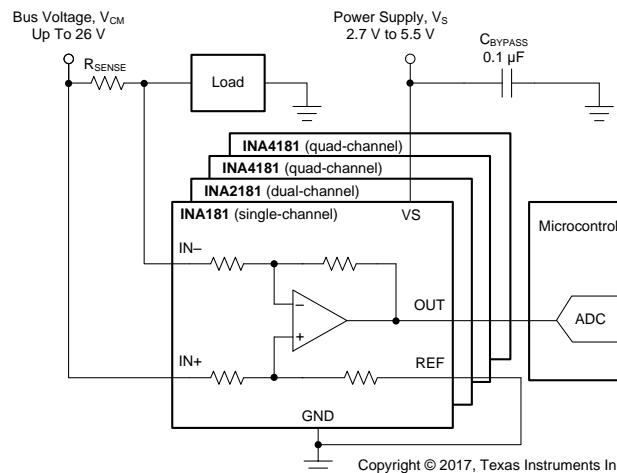
Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
INA181	SOT-23 (6)	2.90 mm x 1.60 mm
INA2181 ⁽²⁾	VSSOP (10)	3.00 mm x 3.00 mm
INA4181 ⁽²⁾	TSSOP (20)	6.50 mm x 4.40 mm

(1) For all available packages, see the package option addendum at the end of the datasheet.

(2) INA2181 and INA4181 are preview devices.

Typical Application Circuit



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4 Revision History

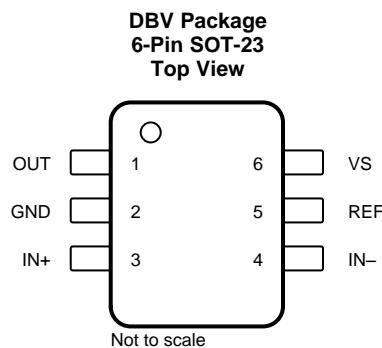
Changes from Revision A (August 2017) to Revision B		Page
• Added INA4181 preview device and associated content to data sheet		1
• Changed design parameter name in Table 3 from "Accuracy" to "Current sensing error" for clarity		25
• Changed "RMS" to "RSS" in reference to equation 7		26

Changes from Original (April 2017) to Revision A		Page
• Added INA2181 preview device and associated content to data sheet		1

5 Device Comparison Table

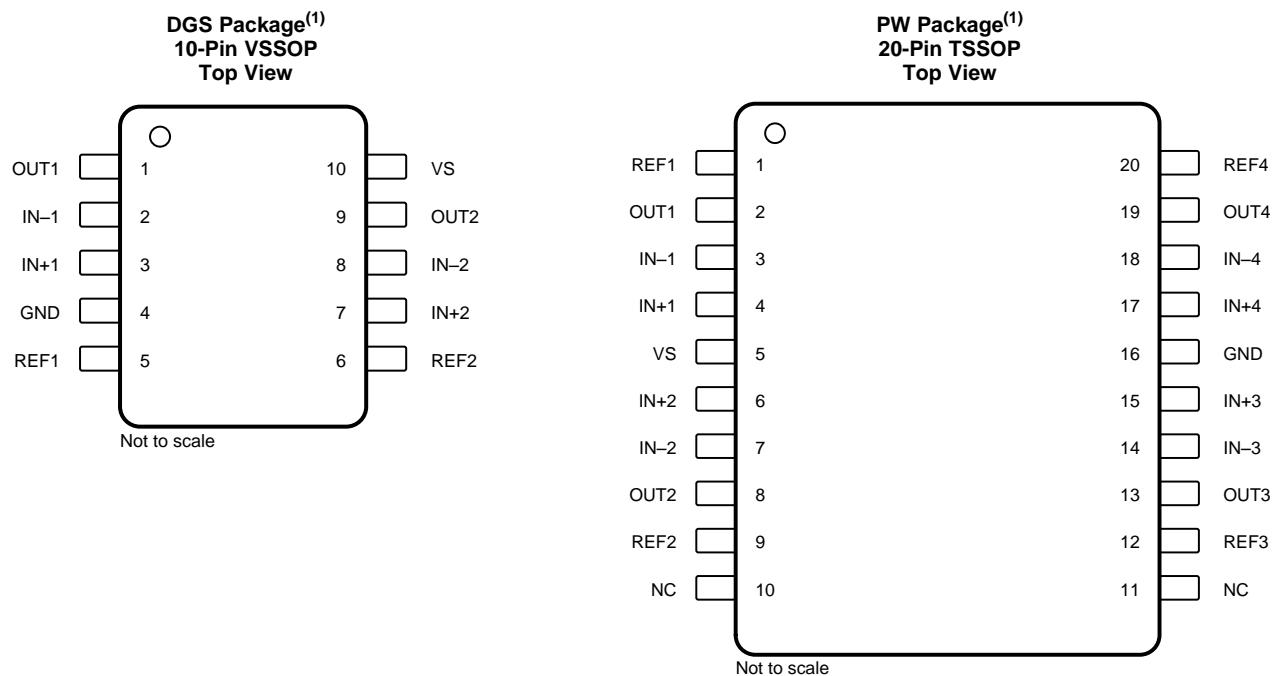
PRODUCT	NUMBER OF CHANNELS	GAIN (V/V)
INA181A1	1	20
INA181A2	1	50
INA181A3	1	100
INA181A4	1	200
INA2181A1	2	20
INA2181A2	2	50
INA2181A3	2	100
INA2181A4	2	200
INA4181A1	4	20
INA4181A2	4	50
INA4181A3	4	100
INA4181A4	4	200

6 Pin Configurations and Functions



Pin Functions: INA181

PIN		TYPE	DESCRIPTION
NAME	NO.		
GND	2	Analog	Ground
IN-	4	Analog input	Current-sense amplifier negative input. For high-side applications, connect to load side of sense resistor. For low-side applications, connect to ground side of sense resistor.
IN+	3	Analog input	Current-sense amplifier positive input. For high-side applications, connect to bus-voltage side of sense resistor. For low-side applications, connect to load side of sense resistor.
OUT	1	Analog output	Output voltage
REF	5	Analog input	Reference input
VS	6	Analog	Power supply, 2.7 V to 5.5 V



(1) INA2181 and INA4181 are preview devices. See the *Package Option Addendum* at the end of this data sheet for more information.

Pin Functions: INA2181 (Dual Channel) and INA4181 (Quad Channel)

PIN			TYPE	DESCRIPTION
NAME	INA2180	INA4180		
GND	4	16	Analog	Ground
IN-1	2	3	Analog input	Current-sense amplifier negative input for channel 1. For high-side applications, connect to load side of channel-1 sense resistor. For low-side applications, connect to ground side of channel-1 sense resistor.
IN+1	3	4	Analog input	Current-sense amplifier positive input for channel 1. For high-side applications, connect to bus-voltage side of channel-1 sense resistor. For low-side applications, connect to load side of channel-1 sense resistor.
IN-2	8	7	Analog input	Current-sense amplifier negative input for channel 2. For high-side applications, connect to load side of channel-2 sense resistor. For low-side applications, connect to ground side of channel-2 sense resistor.
IN+2	7	6	Analog input	Current-sense amplifier positive input for channel 2. For high-side applications, connect to bus-voltage side of channel-2 sense resistor. For low-side applications, connect to load side of channel-2 sense resistor.
IN-3	—	14	Analog input	Current-sense amplifier negative input for channel 3. For high-side applications, connect to load side of channel-3 sense resistor. For low-side applications, connect to ground side of channel-3 sense resistor.
IN+3	—	15	Analog input	Current-sense amplifier positive input for channel 3. For high-side applications, connect to bus-voltage side of channel-3 sense resistor. For low-side applications, connect to load side of channel-3 sense resistor.
IN-4	—	18	Analog input	Current-sense amplifier negative input for channel 4. For high-side applications, connect to load side of channel-4 sense resistor. For low-side applications, connect to ground side of channel-4 sense resistor.
IN+4	—	17	Analog input	Current-sense amplifier positive input for channel 4. For high-side applications, connect to bus-voltage side of channel-4 sense resistor. For low-side applications, connect to load side of channel-4 sense resistor.
NC	—	10, 11	—	NC denotes no internal connection. These pins can be left floating or connected to any voltage between V_S and ground.
OUT1	1	2	Analog output	Channel 1 output voltage
OUT2	9	8	Analog output	Channel 2 output voltage

Pin Functions: INA2181 (Dual Channel) and INA4181 (Quad Channel) (continued)

PIN			TYPE	DESCRIPTION
NAME	INA2180	INA4180		
OUT3	—	13	Analog output	Channel 3 output voltage
OUT4	—	19	Analog output	Channel 4 output voltage
REF1	5	1	Analog input	Channel 1 reference voltage, 0 to V_S
REF2	6	9	Analog input	Channel 2 reference voltage, 0 to V_S
REF3	—	12	Analog input	Channel 3 reference voltage, 0 to V_S
REF4	—	20	Analog input	Channel 4 reference voltage, 0 to V_S
VS	10	5	Analog	Power supply pin, 2.7 V to 5.5 V

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
Supply voltage, V_S		6		V
Analog inputs, IN_+ , IN_- ⁽²⁾	Differential (V_{IN_+}) – (V_{IN_-})	-26	26	V
	Common-mode ⁽³⁾	GND – 0.3	26	
Input voltage range	at REF pin	GND – 0.3	V_S + 0.3	V
Output voltage		GND – 0.3	V_S + 0.3	V
Maximum output current, I_{OUT}		8		mA
Operating free-air temperature, T_A		-55	150	°C
Junction temperature, T_J			150	°C
Storage temperature, T_{STG}		-65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) V_{IN_+} and V_{IN_-} are the voltages at the IN_+ and IN_- pins, respectively.

(3) Input voltage at any pin can exceed the voltage shown if the current at that pin is limited to 5 mA.

7.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	± 3000
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	± 1000

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

		MIN	NOM	MAX	UNIT
V_{CM}	Common-mode input voltage (IN_+ and IN_-)	-0.2	12	26	V
V_S	Operating supply voltage	2.7	5	5.5	V
T_A	Operating free-air temperature	-40		125	°C

7.4 Thermal Information

THERMAL METRIC ⁽¹⁾	INA181	INA2181 (PREVIEW)	INA4181 (PREVIEW)	UNIT	
	DBV (SOT-23)	DGS (VSSOP)	PW (TSSOP)		
	6 PINS	10 PINS	20 PINS		
$R_{\theta JA}$	Junction-to-ambient thermal resistance	198.7	177.3	97.0	°C/W
$R_{\theta JC(\text{top})}$	Junction-to-case (top) thermal resistance	120.9	68.7	37.7	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	52.3	98.4	48.3	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	30.3	12.6	3.6	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	52.0	96.9	47.9	°C/W
$R_{\theta JC(\text{bot})}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

7.5 Electrical Characteristics

at $T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $V_{\text{REF}} = V_S / 2$, $V_{\text{IN+}} = 12\text{ V}$, and $V_{\text{SENSE}} = V_{\text{IN+}} - V_{\text{IN-}}$ (unless otherwise noted)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
INPUT					
CMRR ⁽¹⁾	$V_{\text{IN+}} = 0\text{ V}$ to 26 V , $V_{\text{SENSE}} = 0\text{ mV}$, $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	84	100		dB
V_{OS}	$V_{\text{SENSE}} = 0\text{ mV}$		± 100	± 500	μV
	$V_{\text{SENSE}} = 0\text{ mV}$, $V_{\text{IN+}} = 0\text{ V}$		± 25	± 150	μV
dV_{OS}/dT	$V_{\text{SENSE}} = 0\text{ mV}$, $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	0.2	1		$\mu\text{V}/^\circ\text{C}$
PSRR	$V_S = 2.7\text{ V}$ to 5.5 V , $V_{\text{IN+}} = 12\text{ V}$, $V_{\text{SENSE}} = 0\text{ mV}$		± 8	± 40	$\mu\text{V}/\text{V}$
I_{IB}	$V_{\text{SENSE}} = 0\text{ mV}$, $V_{\text{IN+}} = 0\text{ V}$		-6		μA
	$V_{\text{SENSE}} = 0\text{ mV}$		75		μA
I_{IO}	$V_{\text{SENSE}} = 0\text{ mV}$		± 0.05		μA
OUTPUT					
G	A1 devices		20		V/V
	A2 devices		50		V/V
	A3 devices		100		V/V
	A4 devices		200		V/V
E_G	$V_{\text{OUT}} = 0.5\text{ V}$ to $V_S - 0.5\text{ V}$, $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$		$\pm 0.1\%$	$\pm 1\%$	
Gain error vs temperature		$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	1.5	20	$\text{ppm}/^\circ\text{C}$
Nonlinearity error		$V_{\text{OUT}} = 0.5\text{ V}$ to $V_S - 0.5\text{ V}$		$\pm 0.01\%$	
Maximum capacitive load		No sustained oscillation	1		nF
VOLTAGE OUTPUT ⁽²⁾					
V_{SP}	Swing to V_S power-supply rail ⁽³⁾	$R_L = 10\text{ k}\Omega$ to GND, $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	$(V_S) - 0.02$	$(V_S) - 0.03$	V
V_{SN}	Swing to GND ⁽³⁾	$R_L = 10\text{ k}\Omega$ to GND, $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	$(V_{\text{GND}}) + 0.0005$	$(V_{\text{GND}}) + 0.005$	V
FREQUENCY RESPONSE					
BW	A1 devices, $C_{\text{LOAD}} = 10\text{ pF}$		350		kHz
	A2 devices, $C_{\text{LOAD}} = 10\text{ pF}$		210		kHz
	A3 devices, $C_{\text{LOAD}} = 10\text{ pF}$		150		kHz
	A4 devices, $C_{\text{LOAD}} = 10\text{ pF}$		105		kHz
SR	Slew rate		2		V/ μs
NOISE, RTI ⁽¹⁾					
Voltage noise density			40		$\text{nV}/\sqrt{\text{Hz}}$
POWER SUPPLY					
I_Q	INA181	$V_{\text{SENSE}} = 0\text{ mV}$	195	260	μA
		$V_{\text{SENSE}} = 0\text{ mV}$, $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$		300	μA
	INA2181 (preview)	$V_{\text{SENSE}} = 0\text{ mV}$	340	450	μA
		$V_{\text{SENSE}} = 0\text{ mV}$, $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$		500	μA
	INA4181 (preview)	$V_{\text{SENSE}} = 0\text{ mV}$	690	900	μA
		$V_{\text{SENSE}} = 0\text{ mV}$, $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$		1000	μA

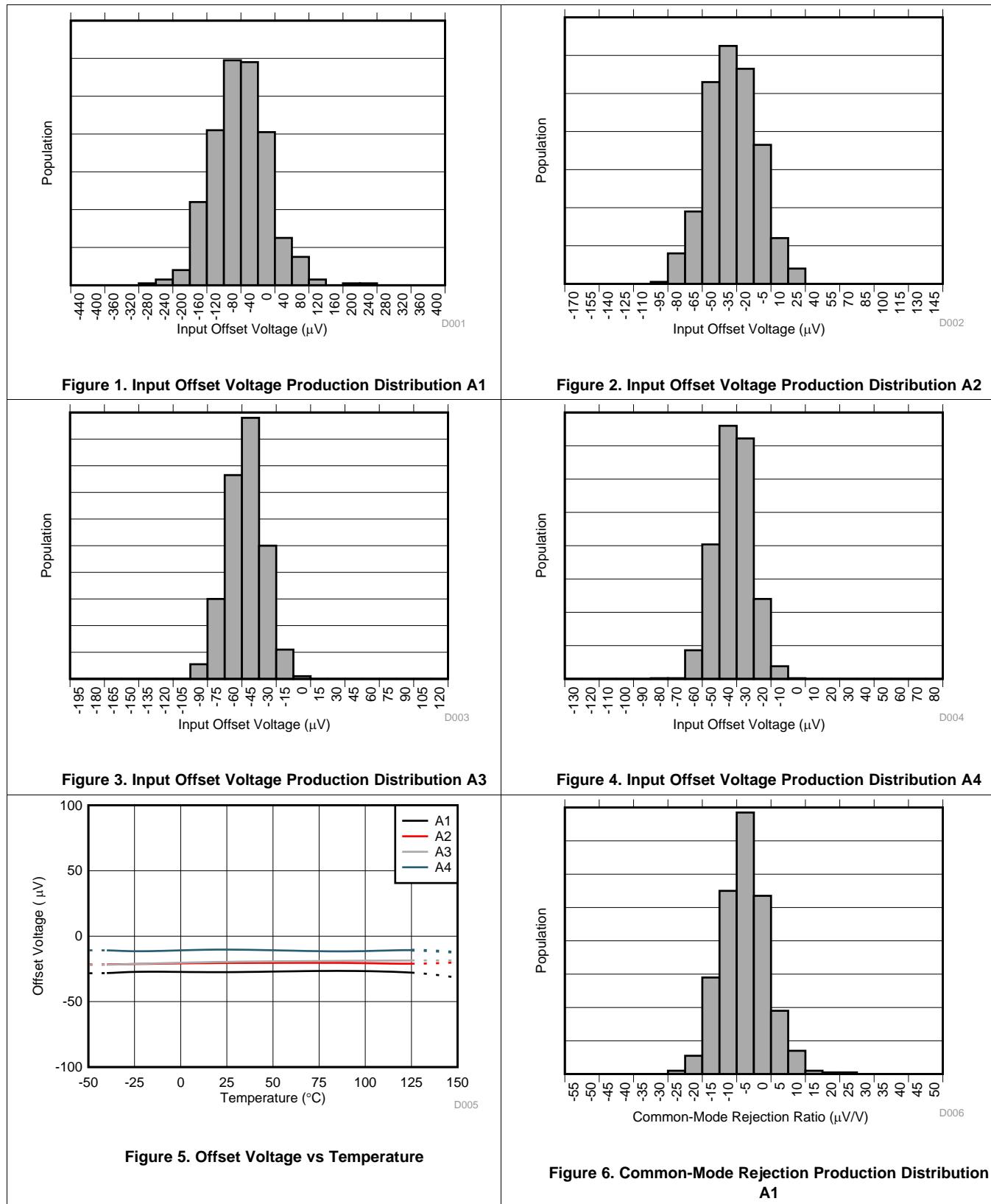
(1) RTI = referred-to-input.

(2) See Figure 19.

(3) Swing specifications are tested with an overdriven input condition.

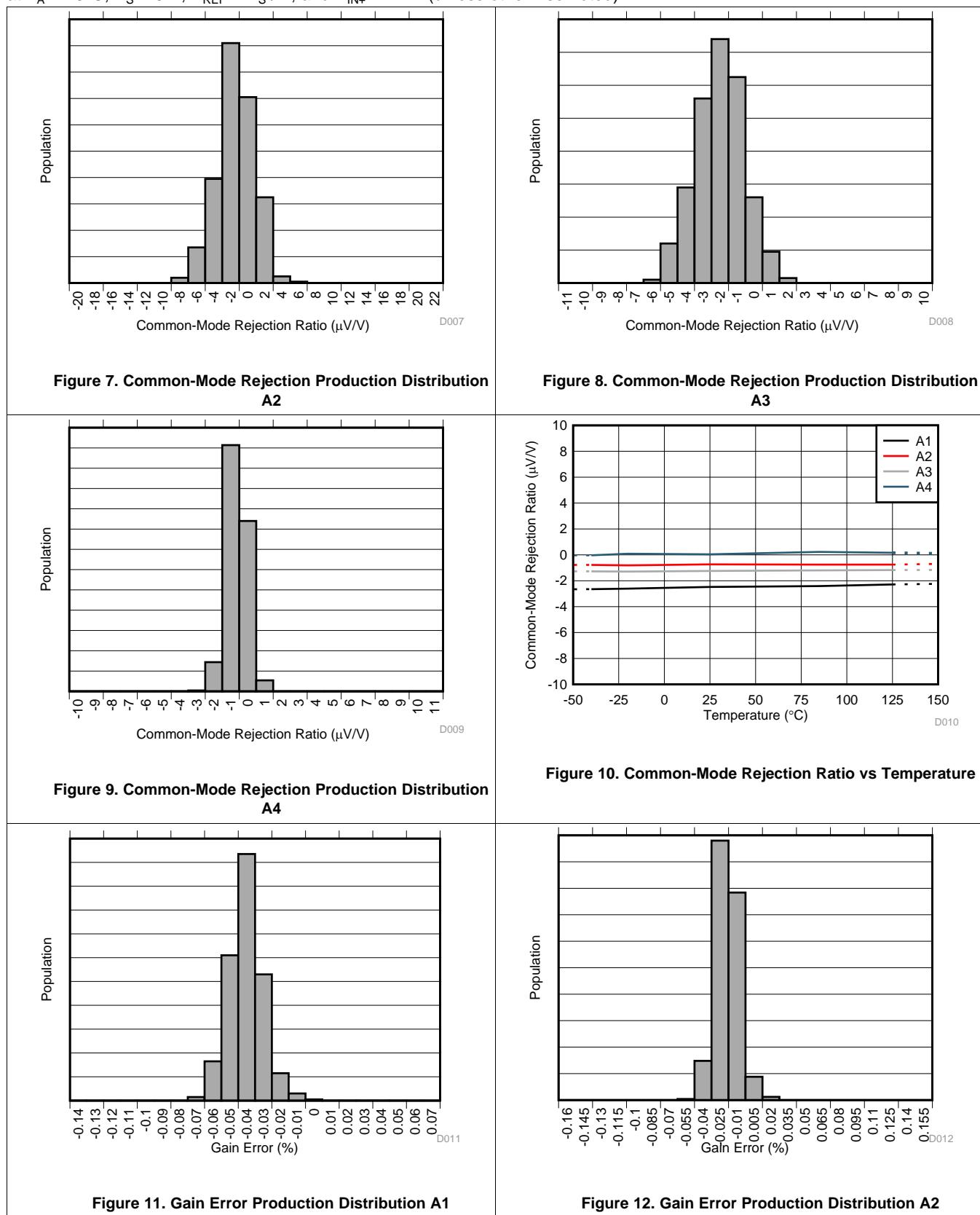
7.6 Typical Characteristics

at $T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $V_{\text{REF}} = V_S / 2$, and $V_{\text{IN+}} = 12\text{ V}$ (unless otherwise noted)



Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $V_S = 5 \text{ V}$, $V_{\text{REF}} = V_S / 2$, and $V_{\text{IN+}} = 12 \text{ V}$ (unless otherwise noted)



Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $V_{\text{REF}} = V_S / 2$, and $V_{\text{IN+}} = 12\text{ V}$ (unless otherwise noted)

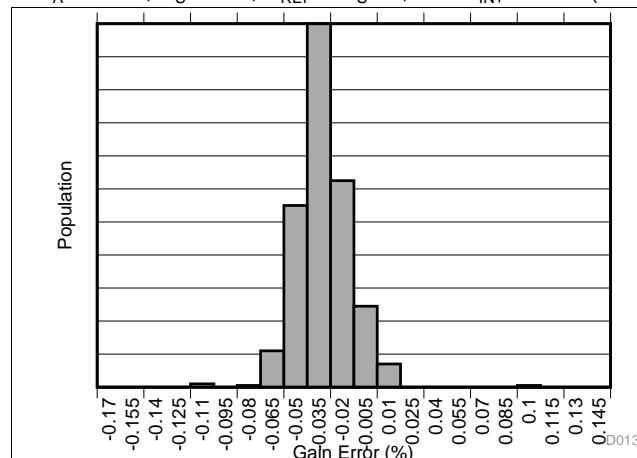


Figure 13. Gain Error Production Distribution A3

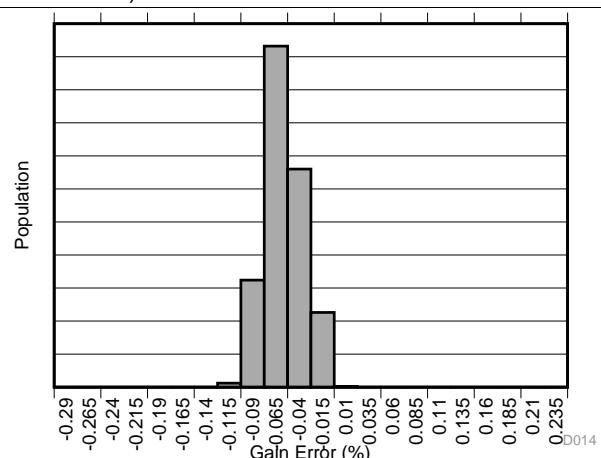


Figure 14. Gain Error Production Distribution A4

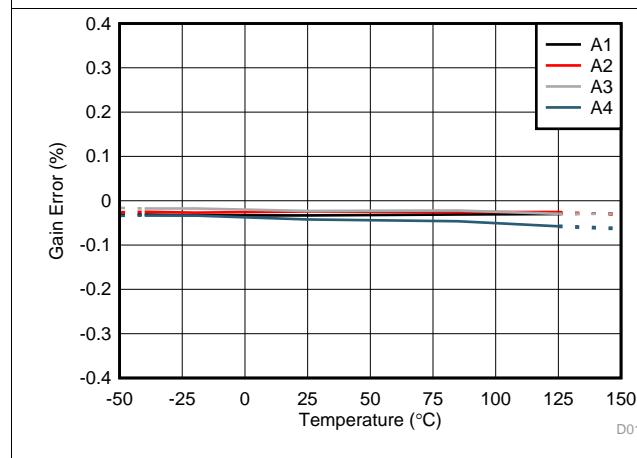


Figure 15. Gain Error vs Temperature

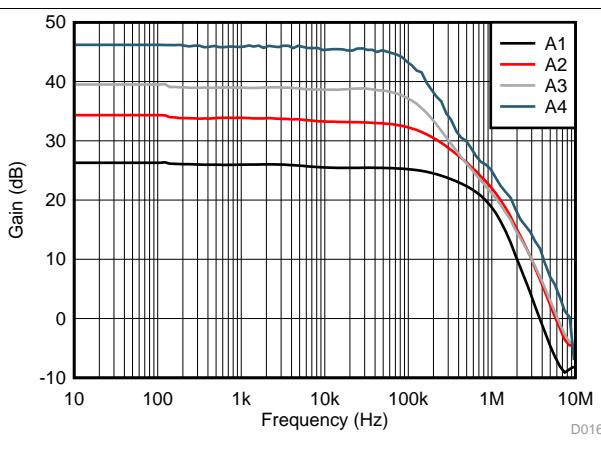


Figure 16. Gain vs Frequency

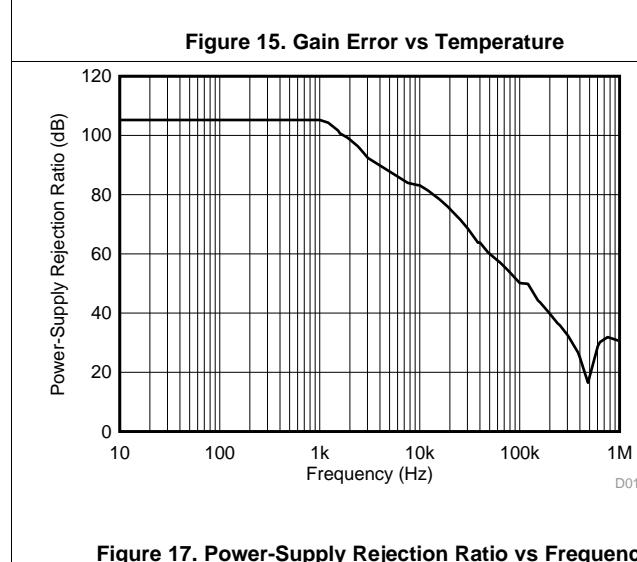


Figure 17. Power-Supply Rejection Ratio vs Frequency

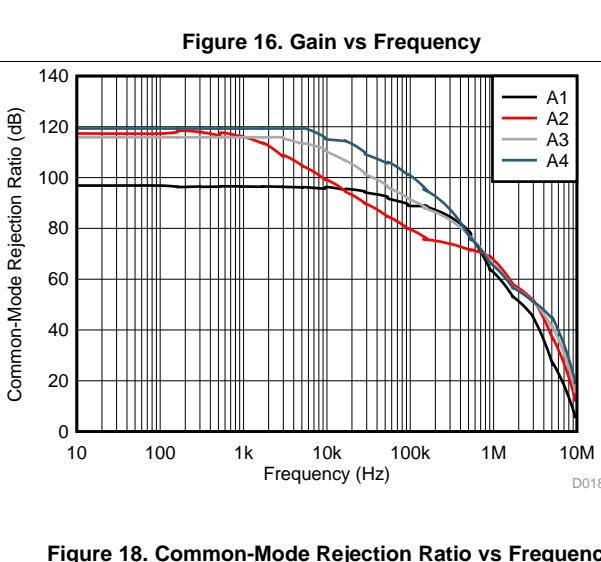


Figure 18. Common-Mode Rejection Ratio vs Frequency

Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $V_{\text{REF}} = V_S / 2$, and $V_{\text{IN+}} = 12\text{ V}$ (unless otherwise noted)

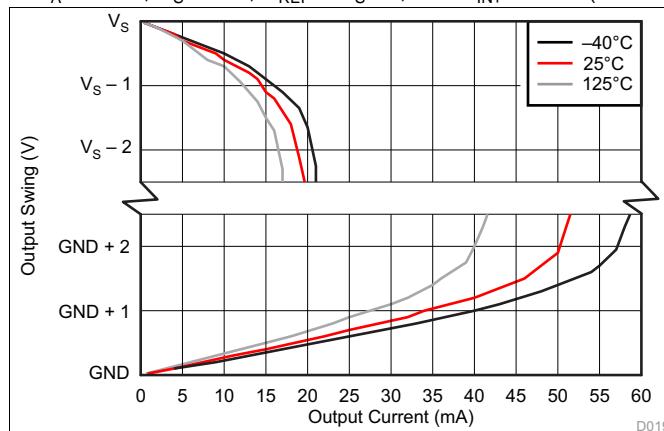


Figure 19. Output Voltage Swing vs Output Current

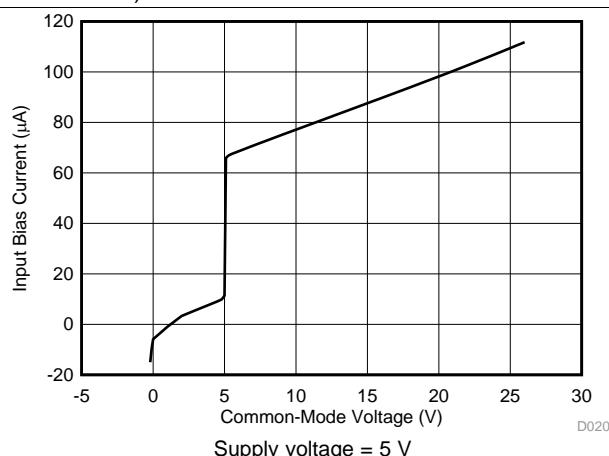


Figure 20. Input Bias Current vs Common-Mode Voltage

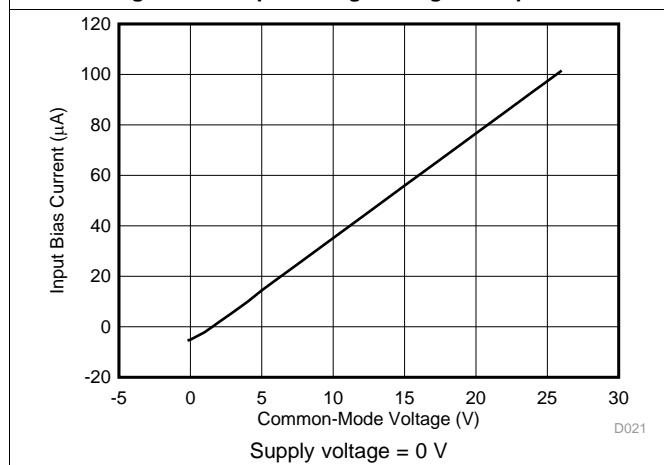


Figure 21. Input Bias Current vs Common-Mode Voltage (Shutdown)

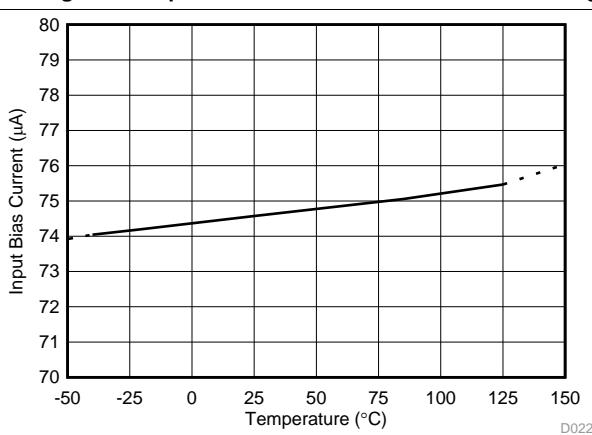


Figure 22. Input Bias Current vs Temperature

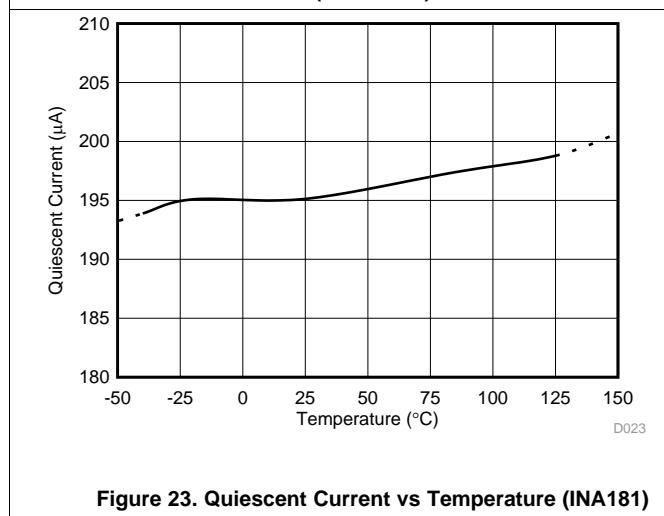


Figure 23. Quiescent Current vs Temperature (INA181)

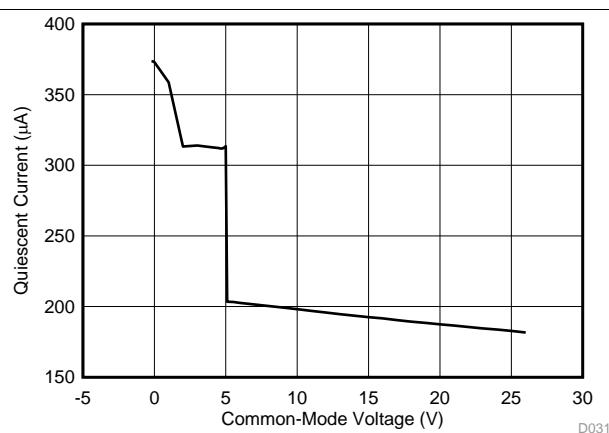


Figure 24. I_Q vs Common-Mode Voltage (INA181)

Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $V_{\text{REF}} = V_S / 2$, and $V_{\text{IN+}} = 12\text{ V}$ (unless otherwise noted)

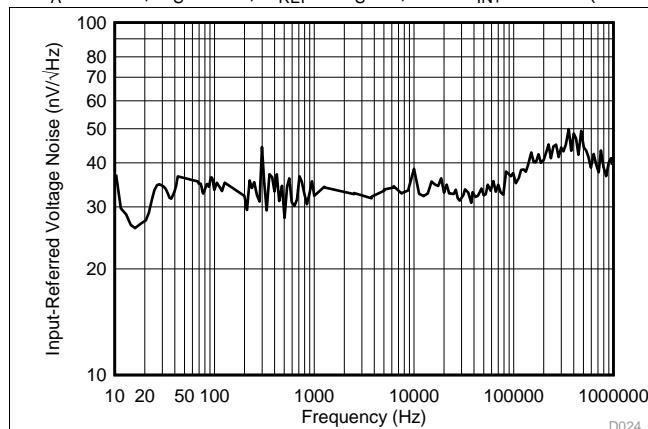


Figure 25. Input-Referred Voltage Noise vs Frequency

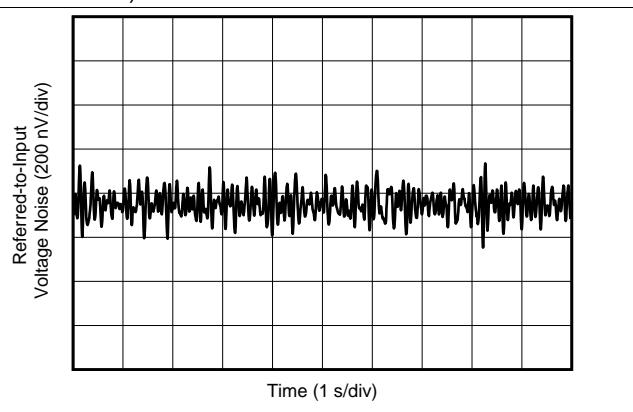


Figure 26. 0.1-Hz to 10-Hz Voltage Noise (Referred-to-Input)

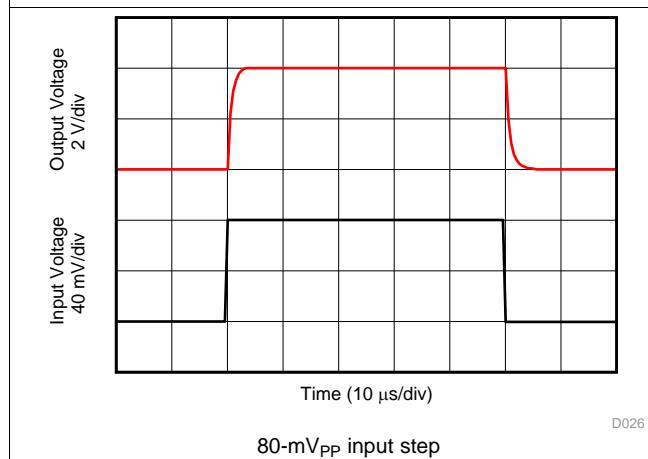


Figure 27. Step Response

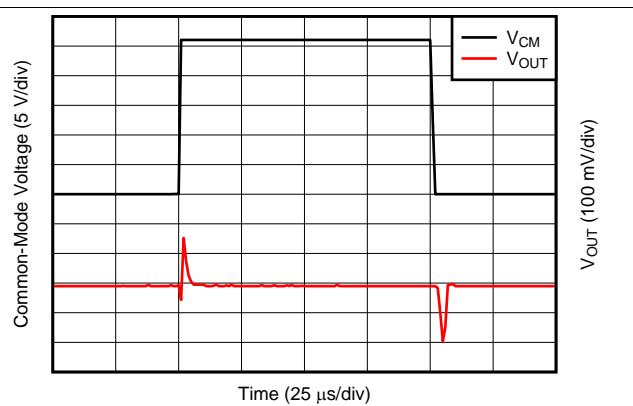


Figure 28. Common-Mode Voltage Transient Response

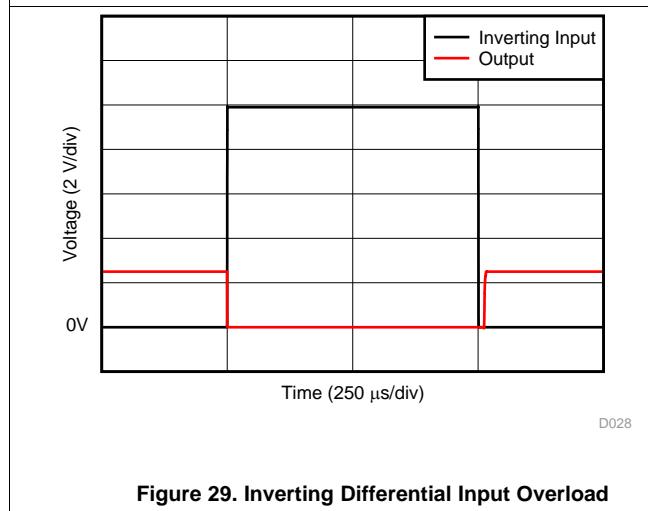


Figure 29. Inverting Differential Input Overload

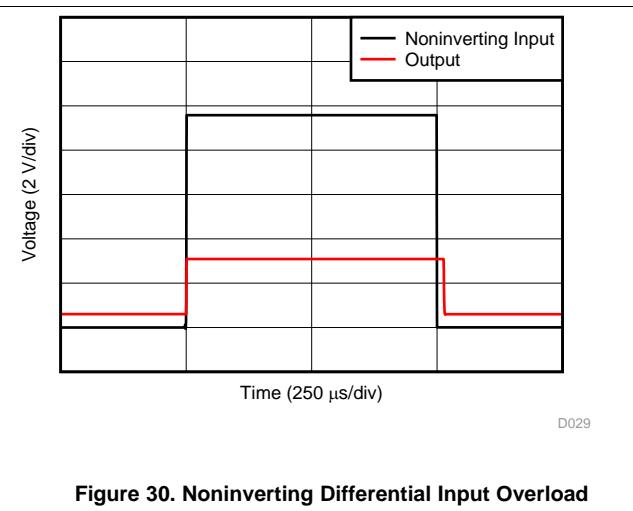
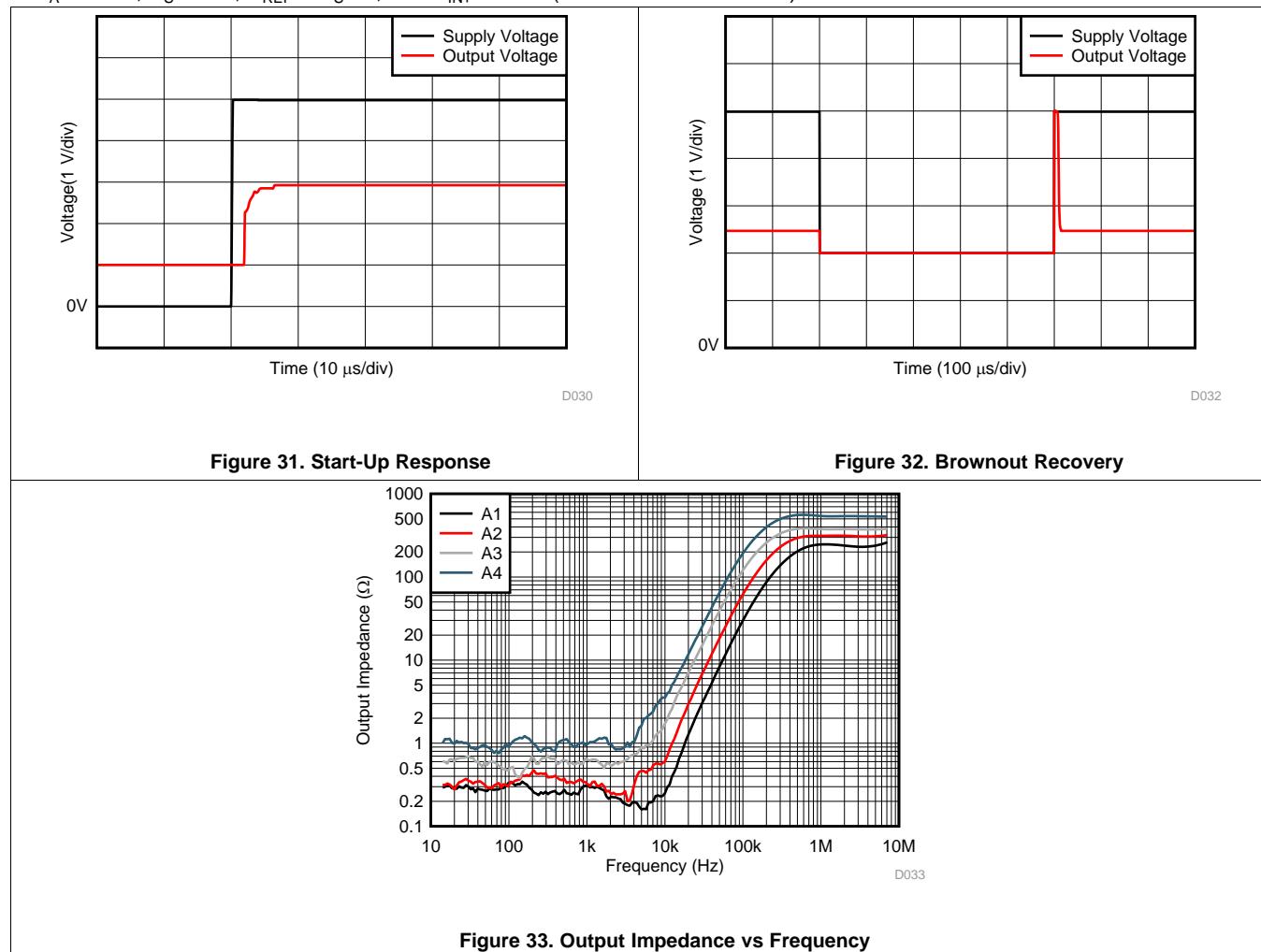


Figure 30. Noninverting Differential Input Overload

Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $V_{\text{REF}} = V_S / 2$, and $V_{\text{IN+}} = 12\text{ V}$ (unless otherwise noted)

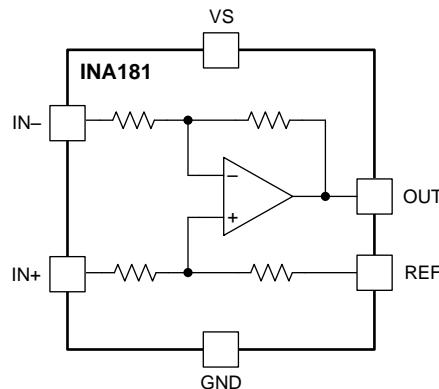


8 Detailed Description

8.1 Overview

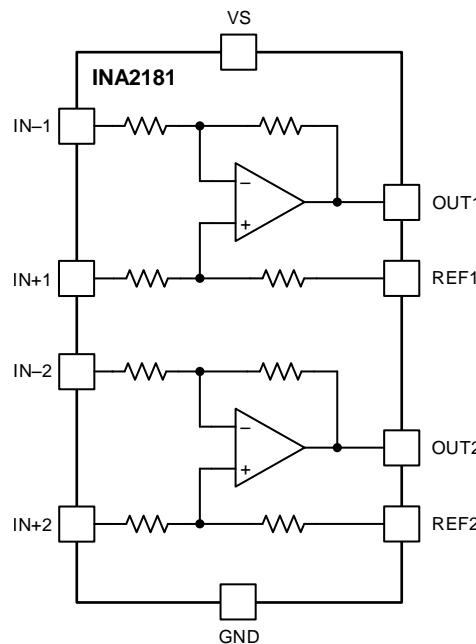
The INA181, INA2181, and INA4181 (INAx181) are 26-V common-mode, current-sensing amplifiers used in both low-side and high-side configurations. These specially-designed, current-sensing amplifiers accurately measure voltages developed across current-sensing resistors on common-mode voltages that far exceed the supply voltage powering the device. Current can be measured on input voltage rails as high as 26 V, and the devices can be powered from supply voltages as low as 2.7 V.

8.2 Functional Block Diagrams



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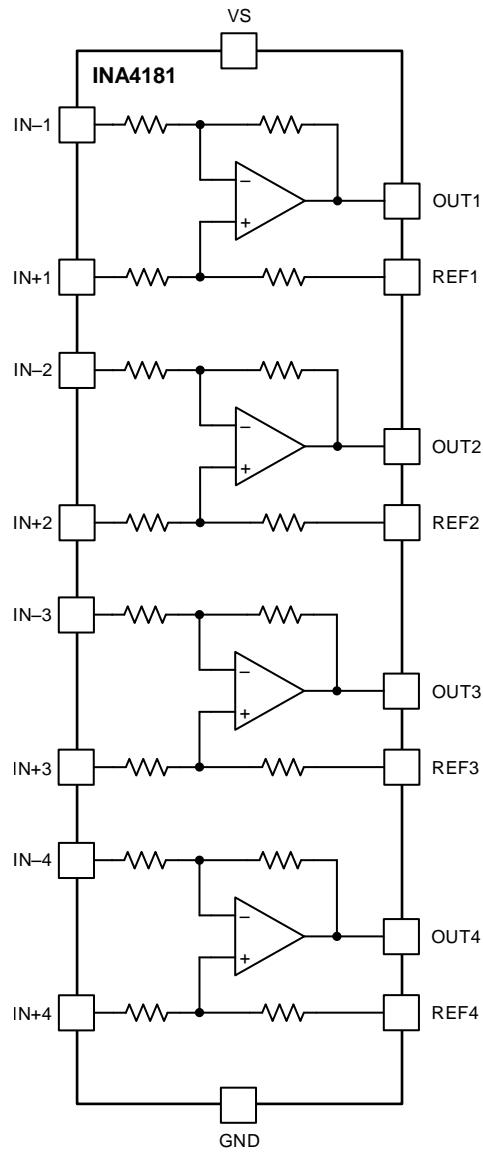
Figure 34. INA181 Functional Block Diagram



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Figure 35. INA2181 Functional Block Diagram

Functional Block Diagrams (continued)



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Figure 36. INA4181 Functional Block Diagram

8.3 Feature Description

8.3.1 High Bandwidth and Slew Rate

The INAx181 support small-signal bandwidths as high as 350 kHz, and large-signal slew rates of 2 V/μs. The ability to detect rapid changes in the sensed current, as well as the ability to quickly slew the output, make the INAx181 a good choice for applications that require a quick response to input current changes. One application that requires high bandwidth and slew rate is low-side motor control, where the ability to follow rapid changing current in the motor allows for more accurate control over a wider operating range. Another application that requires higher bandwidth and slew rates is system fault detection, where the INAx181 are used with an external comparator and a reference to quickly detect when the sensed current is out of range.

8.3.2 Bidirectional Current Monitoring

The INA181 senses current flow through a sense resistor in both directions. The bidirectional current-sensing capability is achieved by applying a voltage at the REF pin to offset the output voltage. A positive differential voltage sensed at the inputs results in an output voltage that is greater than the applied reference voltage; likewise, a negative differential voltage at the inputs results in output voltage that is less than the applied reference voltage. The output voltage of the current-sense amplifier is shown in [Equation 1](#).

$$V_{\text{OUT}} = (I_{\text{LOAD}} \times R_{\text{SENSE}} \times \text{GAIN}) + V_{\text{REF}}$$

where

- I_{LOAD} is the load current to be monitored.
- R_{SENSE} is the current-sense resistor.
- GAIN is the gain option of the selected device.
- V_{REF} is the voltage applied to the REF pin.

(1)

8.3.3 Wide Input Common-Mode Voltage Range

The INAx181 support input common-mode voltages from -0.2 V to $+26$ V. Because of the internal topology, the common-mode range is not restricted by the power-supply voltage (V_S) as long as V_S stays within the operational range of 2.7 V to 5.5 V. The ability to operate with common-mode voltages greater or less than V_S allow the INAx181 to be used in high-side, as well as low-side, current-sensing applications, as shown in [Figure 37](#).

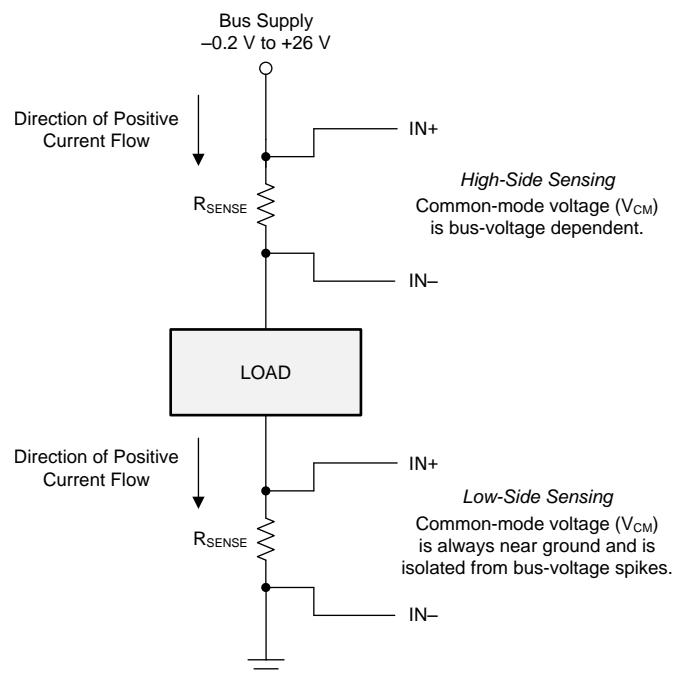


Figure 37. High-Side and Low-Side Sensing Connections

Feature Description (continued)

8.3.4 Precise Low-Side Current Sensing

When used in low-side current sensing applications the offset voltage of the INAx181 is less than 150 μ V. The low offset performance of the INAx181 has several benefits. First, the low offset allows these devices to be used in applications that must measure current over a wide dynamic range. In this case, the low offset improves the accuracy when the sensed currents are on the low end of the measurement range. Another advantage of low offset is the ability to sense lower voltage drop across the sense resistor accurately, thus allowing a lower-value shunt resistor. Lower-value shunt resistors reduce power loss in the current sense circuit, and help improve the power efficiency of the end application.

The gain error of the INAx181 is specified to be within 1% of the actual value. As the sensed voltage becomes much larger than the offset voltage, this voltage becomes the dominant source of error in the current sense measurement.

8.3.5 Rail-to-Rail Output Swing

The INAx181 allow linear current sensing operation with the output close to the supply rail and GND. The maximum specified output swing to the positive rail is 30 mV, and the maximum specified output swing to GND is only 5 mV. In order to compare the output swing of the INAx181 to an equivalent operational amplifier (op amp), the inputs are overdriven to approximate the open-loop condition specified in op amp data sheets. The current-sense amplifier is a closed-loop system; therefore, the output swing to GND can be limited by the product of the offset voltage and amplifier gain during unidirectional operation ($V_{REF} = 0$ V).

For devices that have positive offset voltages, the swing to GND is limited by the larger of either the offset voltage multiplied by the gain or the swing to GND specified in the *Electrical Characteristics* table.

For example, in an application where the INA181A4 (gain = 200 V/V) is used for low-side current sensing and the device has an offset of 40 μ V, the product of the device offset and gain results in a value of 8 mV, greater than the specified negative swing value. Therefore, the swing to GND for this example is 8 mV. If the same device has an offset of -40 μ V, then the calculated zero differential signal is -8 mV. In this case, the offset helps overdrive the swing in the negative direction, and swing performance is consistent with the value specified in the *Electrical Characteristics* table.

The offset voltage is a function of the common-mode voltage as determined by the CMRR specification; therefore, the offset voltage increases when higher common-mode voltages are present. The increase in offset voltage limits how low the output voltage can go during a zero-current condition when operating at higher common-mode voltages with $V_{REF} = 0$ V. The typical limitation of the zero-current output voltage vs common-mode voltage for each gain option is shown in [Figure 38](#).

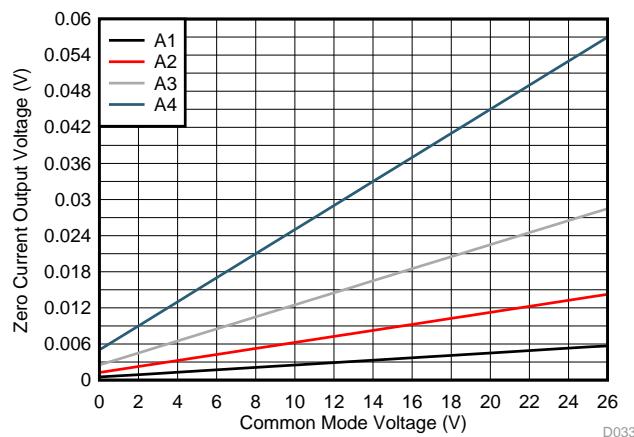


Figure 38. Zero-Current Output Voltage vs Common-Mode Voltage

8.4 Device Functional Modes

8.4.1 Normal Mode

The INAx181 are in normal operation when the following conditions are met:

- The power supply voltage (V_S) is between 2.7 V and 5.5 V.
- The common-mode voltage (V_{CM}) is within the specified range of -0.2 V to $+26$ V.
- The maximum differential input signal times gain plus V_{REF} is less than V_S minus the output voltage swing to V_S .
- The minimum differential input signal times gain plus V_{REF} is greater than the swing to GND (see the *Rail-to-Rail Output Swing* section).

During normal operation, these devices produce an output voltage that is the *gained-up* representation of the difference voltage from IN+ to IN– plus the reference voltage at V_{REF} .

8.4.2 Unidirectional Mode

These devices can be configured to monitor current flowing in one direction (unidirectional) or in both directions (bidirectional) depending on how the REF pin is configured. The most common case is unidirectional where the output is set to ground when no current is flowing by connecting the REF pin to ground, as shown in [Figure 39](#). When the current flows from the bus supply to the load, the input signal across IN+ to IN– increases, and causes the output voltage at the OUT pin to increase.

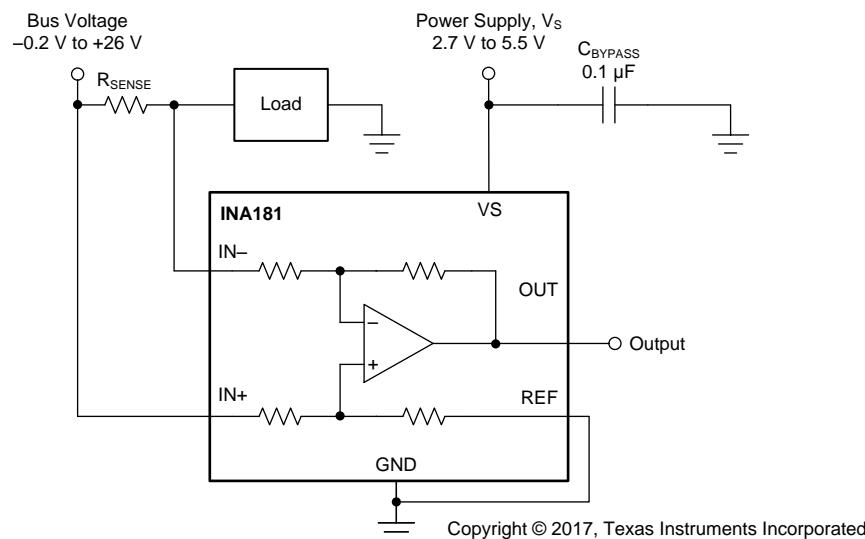


Figure 39. Unidirectional Application

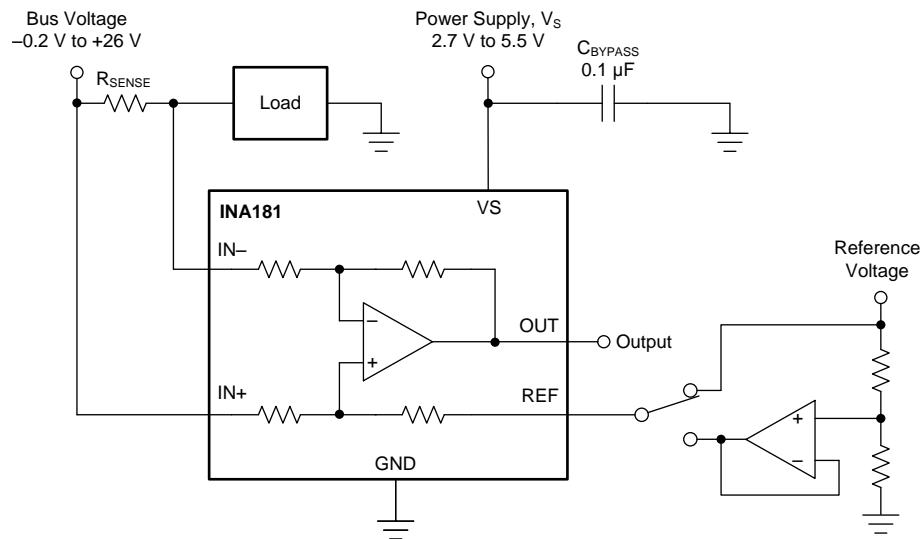
The linear range of the output stage is limited by how close the output voltage can approach ground under zero input conditions. In unidirectional applications where measuring very low input currents is desirable, bias the REF pin to a convenient value above 50 mV to get the output into the linear range of the device. To limit common-mode rejection errors, buffer the reference voltage connected to the REF pin.

A less-frequently used output biasing method is to connect the REF pin to the power-supply voltage, V_S . This method results in the output voltage saturating at 200 mV less than the supply voltage when no differential input signal is present. This method is similar to the output saturated low condition with no input signal when the REF pin is connected to ground. The output voltage in this configuration only responds to negative currents that develop negative differential input voltage relative to the device IN– pin. Under these conditions, when the differential input signal increases negatively, the output voltage moves downward from the saturated supply voltage. The voltage applied to the REF pin must not exceed V_S .

Device Functional Modes (continued)

8.4.3 Bidirectional Mode

The INAx181 are bidirectional, current-sense amplifiers capable of measuring currents through a resistive shunt in two directions. This bidirectional monitoring is common in applications that include charging and discharging operations where the current flowing through the resistor can change directions.



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Figure 40. Bidirectional Application

The ability to measure this current flowing in both directions is enabled by applying a voltage to the REF pin, as shown in [Figure 40](#). The voltage applied to REF (V_{REF}) sets the output state that corresponds to the zero-input level state. The output then responds by increasing above V_{REF} for positive differential signals (relative to the IN- pin) and responds by decreasing below V_{REF} for negative differential signals. This reference voltage applied to the REF pin can be set anywhere between 0 V to V_S . For bidirectional applications, V_{REF} is typically set at mid-scale for equal signal range in both current directions. In some cases, however, V_{REF} is set at a voltage other than mid-scale when the bidirectional current and corresponding output signal do not need to be symmetrical.

8.4.4 Input Differential Overload

If the differential input voltage ($V_{IN+} - V_{IN-}$) times gain exceeds the voltage swing specification, the INAx181 drive the output as close as possible to the positive supply or ground, and does not provide accurate measurement of the differential input voltage. If this input overload occurs during normal circuit operation, then reduce the value of the shunt resistor or use a lower-gain version with the chosen sense resistor to avoid this mode of operation. If a differential overload occurs in a fault event, then the output of the INAx181 returns to the expected value approximately 20 μ s after the fault condition is removed.

Device Functional Modes (continued)

8.4.5 Shutdown Mode

Although the INAx181 do not have a shutdown pin, the low power consumption of these devices allows the output of a logic gate or transistor switch to power the INAx181. This gate or switch turns on and off the INAx181 power-supply quiescent current.

However, in current shunt monitoring applications, there is also a concern for how much current is drained from the shunt circuit in shutdown conditions. Evaluating this current drain involves considering the simplified schematic of the INAx181 in shutdown mode, as shown in [Figure 41](#).

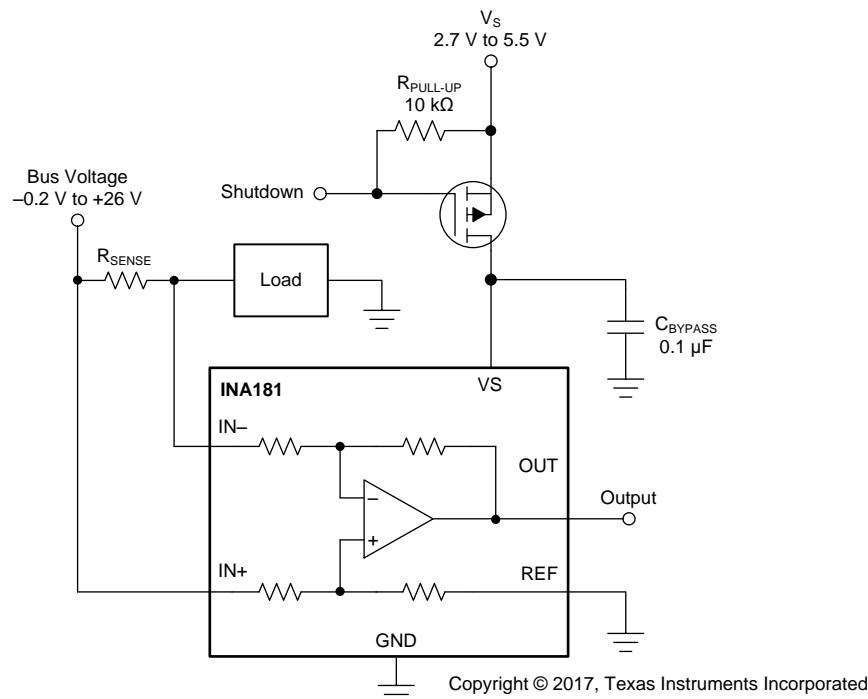


Figure 41. Basic Circuit to Shut Down the INA181 With a Grounded Reference

There is typically more than 500 kΩ of impedance (from the combination of 500-kΩ feedback and input gain set resistors) from each input of the INAx181 to the OUT pin and to the REF pin. The amount of current flowing through these pins depends on the voltage at the connection. For example, if the REF pin is grounded, the calculation of the effect of the 500 kΩ impedance from the shunt to ground is straightforward. However, if the reference is powered while the INAx181 is in shutdown mode, instead of assuming 500 kΩ to ground, assume 500 kΩ to the reference voltage.

Regarding the 500-kΩ path to the output pin, the output stage of a disabled INAx181 does constitute a good path to ground. Consequently, this current is directly proportional to a shunt common-mode voltage present across a 500-kΩ resistor.

As a final note, as long as the shunt common-mode voltage is greater than V_S when the device is powered up, there is an additional and well-matched 55-μA typical current that flows in each of the inputs. If less than V_S , the common-mode input currents are negligible, and the only current effects are the result of the 500-kΩ resistors.

9 Application and Implementation

NOTE

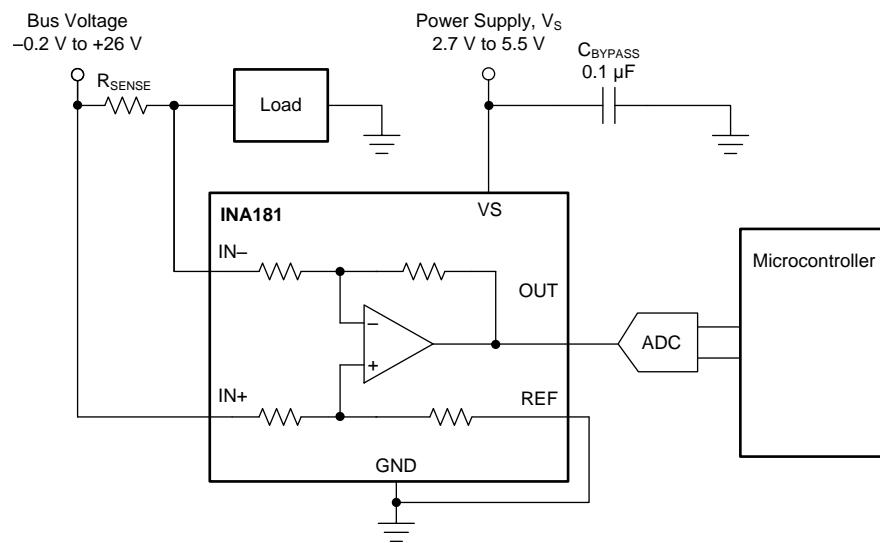
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The INAx181 amplify the voltage developed across a current-sensing resistor as current flows through the resistor to the load or ground. The ability to drive the reference pin to adjust the functionality of the output signal offers multiple configurations, as discussed in previous sections.

9.1.1 Basic Connections

Figure 42 shows the basic connections of the INA181. Connect the input pins (IN+ and IN–) as closely as possible to the shunt resistor to minimize any resistance in series with the shunt resistor.



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NOTE: To help eliminate ground offset errors between the device and the analog-to-digital converter (ADC), connect the REF pin to the ADC reference input and then to ground.

Figure 42. Basic Connections for the INA181

A power-supply bypass capacitor of at least 0.1 μ F is required for proper operation. Applications with noisy or high-impedance power supplies may require additional decoupling capacitors to reject power-supply noise. Connect bypass capacitors close to the device pins.

Application Information (continued)

9.1.2 R_{SENSE} and Device Gain Selection

The accuracy of the INAx181 is maximized by choosing the current-sense resistor to be as large as possible. A large sense resistor maximizes the differential input signal for a given amount of current flow and reduces the error contribution of the offset voltage. However, there are practical limits as to how large the current-sense resistor can be in a given application. The INAx181 have typical input bias currents of 75 μ A for each input when operated at a 12-V common-mode voltage input. When large current-sense resistors are used, these bias currents cause increased offset error and reduced common-mode rejection. Therefore, using current-sense resistors larger than a few ohms is generally not recommended for applications that require current-monitoring accuracy. A second common restriction on the value of the current-sense resistor is the maximum allowable power dissipation that is budgeted for the resistor. [Equation 2](#) gives the maximum value for the current sense resistor for a given power dissipation budget:

$$R_{SENSE} < \frac{PD_{MAX}}{I_{MAX}^2}$$

where:

- PD_{MAX} is the maximum allowable power dissipation in R_{SENSE} .
- I_{MAX} is the maximum current that will flow through R_{SENSE} . (2)

An additional limitation on the size of the current-sense resistor and device gain is due to the power-supply voltage, V_S , and device swing to rail limitations. In order to make sure that the current-sense signal is properly passed to the output, both positive and negative output swing limitations must be examined. [Equation 3](#) provides the maximum values of R_{SENSE} and GAIN to keep the device from hitting the positive swing limitation.

$$I_{MAX} \times R_{SENSE} \times GAIN < V_S - V_{SP} - V_{REF}$$

where:

- I_{MAX} is the maximum current that will flow through R_{SENSE} .
- GAIN is the gain of the current sense-amplifier.
- V_S is the minimum supply voltage of the device.
- V_{SP} is the positive output swing as specified in the data sheet.
- V_{REF} is the externally applied voltage on the REF pin. (3)

To avoid positive output swing limitations when selecting the value of R_{SENSE} , there is always a trade-off between the value of the sense resistor and the gain of the device under consideration. If the sense resistor selected for the maximum power dissipation is too large, then it is possible to select a lower-gain device in order to avoid positive swing limitations.

The negative swing limitation places a limit on how small of a sense resistor can be used in a given application. [Equation 4](#) provides the limit on the minimum size of the sense resistor.

$$I_{MIN} \times R_{SENSE} \times GAIN > V_{SN} - V_{REF}$$

where:

- I_{MIN} is the minimum current that will flow through R_{SENSE} .
- GAIN is the gain of the current sense amplifier.
- V_{SN} is the negative output swing of the device (see [Rail-to-Rail Output Swing](#)).
- V_{REF} is the externally applied voltage on the REF pin. (4)

In addition to adjusting the offset and gain, the voltage applied to the REF pin can be slightly increased to avoid negative swing limitations.

Application Information (continued)

9.1.3 Signal Filtering

Provided that the INAx181 output is connected to a high impedance input, the best location to filter is at the device output using a simple RC network from OUT to GND. Filtering at the output attenuates high-frequency disturbances in the common-mode voltage, differential input signal, and INAx181 power-supply voltage. If filtering at the output is not possible, or filtering of only the differential input signal is required, it is possible to apply a filter at the input pins of the device. [Figure 43](#) provides an example of how a filter can be used on the input pins of the device.

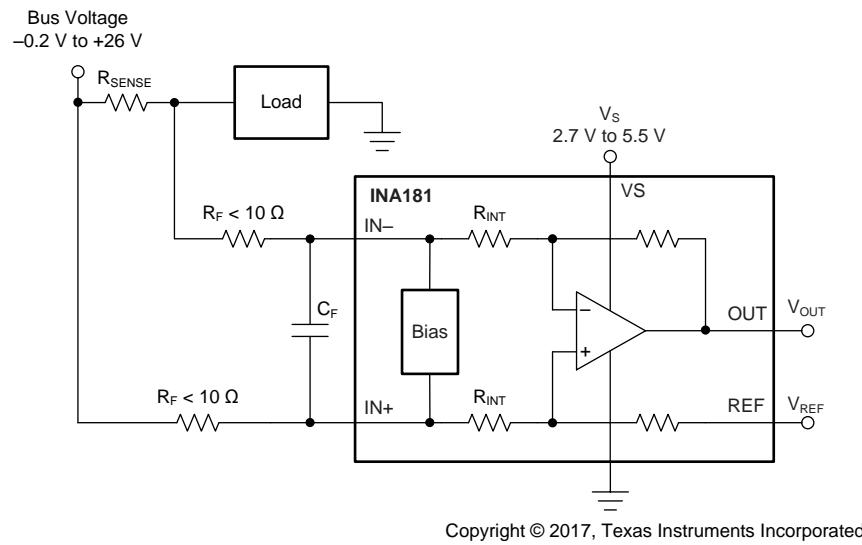


Figure 43. Filter at Input Pins

The addition of external series resistance creates an additional error in the measurement; therefore, the value of these series resistors must be kept to $10\ \Omega$ (or less, if possible) to reduce impact to accuracy. The internal bias network shown in [Figure 43](#) present at the input pins creates a mismatch in input bias currents when a differential voltage is applied between the input pins. If additional external series filter resistors are added to the circuit, the mismatch in bias currents results in a mismatch of voltage drops across the filter resistors. This mismatch creates a differential error voltage that subtracts from the voltage developed across the shunt resistor. This error results in a voltage at the device input pins that is different than the voltage developed across the shunt resistor. Without the additional series resistance, the mismatch in input bias currents has little effect on device operation. The amount of error these external filter resistors add to the measurement can be calculated using [Equation 6](#), where the gain error factor is calculated using [Equation 5](#).

The amount of variance in the differential voltage present at the device input relative to the voltage developed at the shunt resistor is based both on the external series resistance (R_F) value as well as internal input resistor R_{INT} , as shown in [Figure 43](#). The reduction of the shunt voltage reaching the device input pins appears as a gain error when comparing the output voltage relative to the voltage across the shunt resistor. A factor can be calculated to determine the amount of gain error that is introduced by the addition of external series resistance. Calculate the expected deviation from the shunt voltage to what is measured at the device input pins is given using [Equation 5](#):

$$\text{Gain Error Factor} = \frac{1250 \times R_{INT}}{(1250 \times R_F) + (1250 \times R_{INT}) + (R_F \times R_{INT})}$$

where:

- R_{INT} is the internal input resistor.
- R_F is the external series resistance. (5)

Application Information (continued)

With the adjustment factor from [Equation 5](#), including the device internal input resistance, this factor varies with each gain version, as shown in [Table 1](#). Each individual device gain error factor is shown in [Table 2](#).

Table 1. Input Resistance

PRODUCT	GAIN	R _{INT} (kΩ)
INAx181A1	20	25
INAx181A2	50	10
INAx181A3	100	5
INAx181A4	200	2.5

Table 2. Device Gain Error Factor

PRODUCT	SIMPLIFIED GAIN ERROR FACTOR
INAx181A1	$\frac{25000}{(21 \times R_F) + 25000}$
INAx181A2	$\frac{10000}{(9 \times R_F) + 10000}$
INAx181A3	$\frac{1000}{R_F + 1000}$
INAx181A4	$\frac{2500}{(3 \times R_F) + 2500}$

The gain error that can be expected from the addition of the external series resistors can then be calculated based on [Equation 6](#):

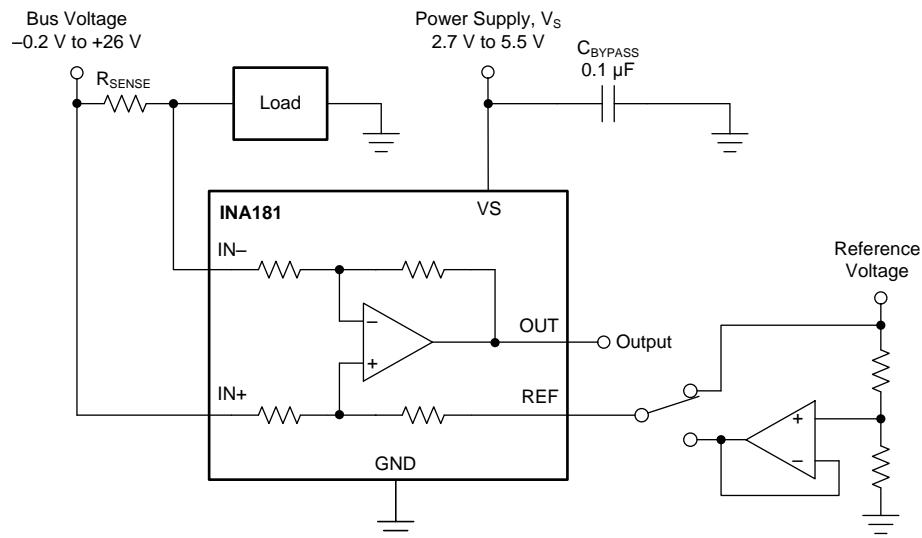
$$\text{Gain Error (\%)} = 100 - (100 \times \text{Gain Error Factor}) \quad (6)$$

For example, using an INA181A2 and the corresponding gain error equation from [Table 2](#), a series resistance of 10 Ω results in a gain error factor of 0.991. The corresponding gain error is then calculated using [Equation 6](#), resulting in an additional gain error of approximately 0.89% solely because of the external 10-Ω series resistors.

9.2 Typical Applications

9.2.1 Measuring Bidirectional Current

One application for the INAx181 is to monitor bidirectional currents. Bidirectional currents are present in systems that have to monitor currents in both directions; common examples are monitoring the charging and discharging of batteries and bidirectional current monitoring in motor control. The device configuration for bidirectional current monitoring is shown in [Figure 44](#). Applying stable REF pin voltage closer to the middle of device supply voltage allows both positive- and negative-current monitoring, as shown in this configuration. Configure the INAx181 to monitor unidirectional currents by grounding the REF pin.



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Figure 44. Measuring Bidirectional Current

9.2.1.1 Design Requirements

The design requirements for the circuit shown in [Figure 44](#), are listed in [Table 3](#)

Table 3. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Power-supply voltage, V_S	5 V
Bus supply rail, V_{CM}	12 V
R_{SENSE} power loss	< 450 mW
Maximum sense current, I_{MAX}	±20 A
Current sensing error	Less than 3.5% at maximum current, $T_J = 25^\circ\text{C}$
Small-signal bandwidth	> 100 kHz

9.2.1.2 Detailed Design Procedure

The maximum value of the current sense resistor is calculated based on the maximum power loss requirement. By applying [Equation 2](#), the maximum value of the current-sense resistor is calculated to be $1.125 \text{ m}\Omega$. This is the maximum value for sense resistor R_{SENSE} ; therefore, select R_{SENSE} to be $1 \text{ m}\Omega$ because it is the closest standard resistor value that meets the power-loss requirement.

The next step is to select the appropriate gain and reduce R_{SENSE} , if needed, to keep the output signal swing within the V_S range. The design requirements call for bidirectional current monitoring; therefore, a voltage between 0 and V_S must be applied to the REF pin. The bidirectional currents monitored are symmetric around 0 (that is, $\pm 20 \text{ A}$); therefore, the ideal voltage to apply to V_{REF} is $V_S / 2$ or 2.5 V . If the positive current is greater than the negative current, using a lower voltage on V_{REF} has the benefit of maximizing the output swing for the given range of expected currents. Using [Equation 3](#), and given that $I_{MAX} = 20 \text{ A}$, $R_{SENSE} = 1 \text{ m}\Omega$, and $V_{REF} = 2.5 \text{ V}$

V , the maximum current-sense gain calculated to avoid the positive swing-to-rail limitations on the output is 122.5. Likewise, using [Equation 4](#) for the negative-swing limitation results in a maximum gain of 124.75. Selecting the gain-of-100 device maximizes the output range while staying within the output swing range. If the maximum calculated gains are slightly less than 100, the value of the current-sense resistor can be reduced to keep the output from hitting the output-swing limitations.

To calculate the accuracy at peak current, the two factors that must be determined are the gain error and the offset error. The gain error of the INAx181 is specified to be a maximum of 1%. The error due to the offset is constant, and is specified to be 500 μ V (maximum) for the conditions where $V_{CM} = 12$ V and $V_S = 5$ V. Using [Equation 7](#), the percentage error contribution of the offset voltage is calculated to be 2.5%, with total offset error = 500 μ V, $R_{SENSE} = 1$ m Ω , and $I_{SENSE} = 20$ A.

$$\text{Total Offset Error (\%)} = \frac{\text{Total Offset Error (V)}}{I_{SENSE} \times R_{SENSE}} \times 100\% \quad (7)$$

One method of calculating the total error is to add the gain error to the percentage contribution of the offset error. However, in this case, the gain error and the offset error do not have an influence or correlation to each other. A more statistically accurate method of calculating the total error is to use the RSS sum of the errors, as shown in [Equation 8](#):

$$\text{Total Error (\%)} = \sqrt{\text{Total Gain Error (\%)}^2 + \text{Total Offset Error (\%)}^2} \quad (8)$$

After applying [Equation 8](#), the total current sense error at maximum current is calculated to be 2.7%, and that is less than the design example requirement of 3.5%.

The INA181A3 (gain = 100) also has a bandwidth of 150 kHz that meets the small-signal bandwidth requirement of 100 kHz. If higher bandwidth is required, lower-gain devices can be used at the expense of either reduced output voltage range or an increased value of R_{SENSE} .

9.2.1.3 Application Curve

An example output response of a bidirectional configuration is shown in [Figure 45](#). With the REF pin connected to a reference voltage (2.5 V in this case), the output voltage is biased upwards by this reference level. The output rises above the reference voltage for positive differential input signals, and falls below the reference voltage for negative differential input signals.

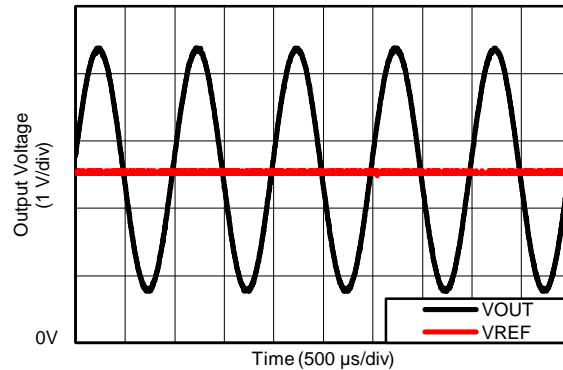


Figure 45. Bidirectional Application Output Response

9.2.2 Summing Multiple Currents

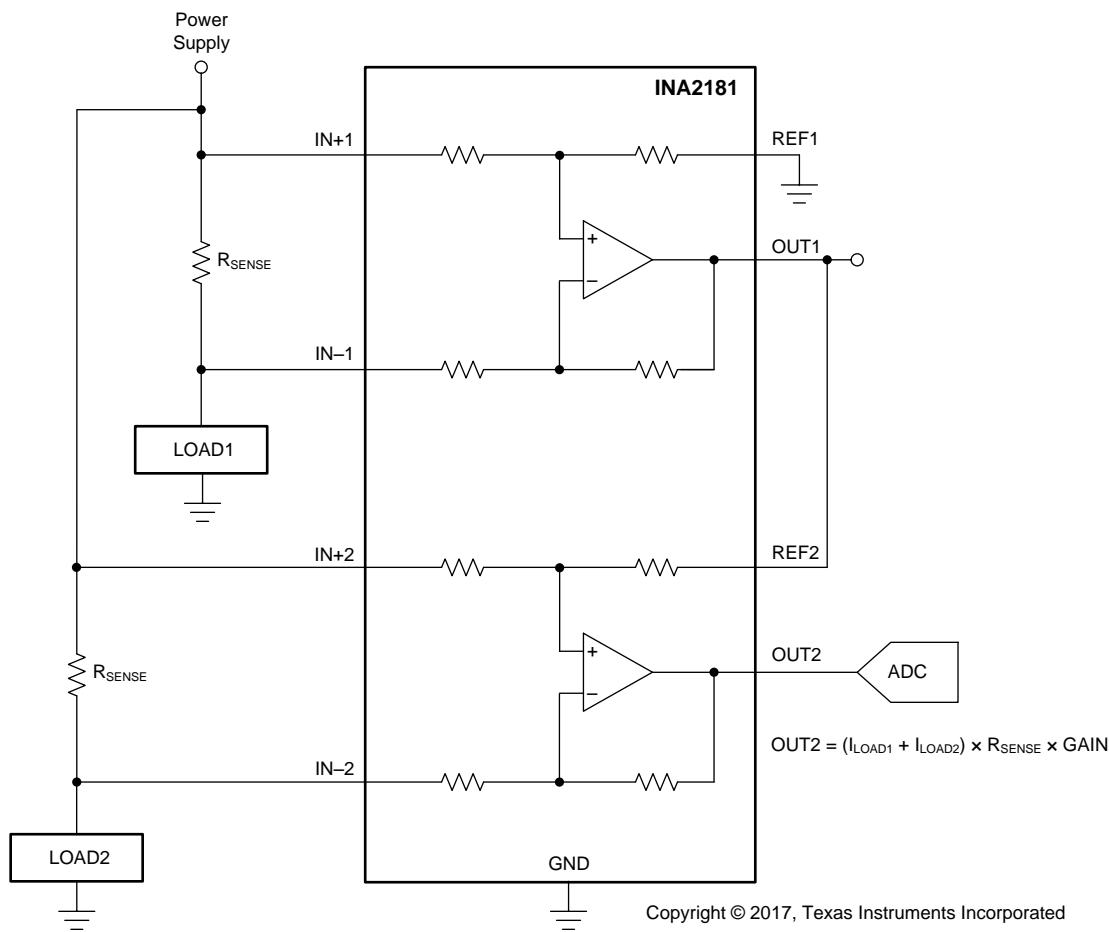
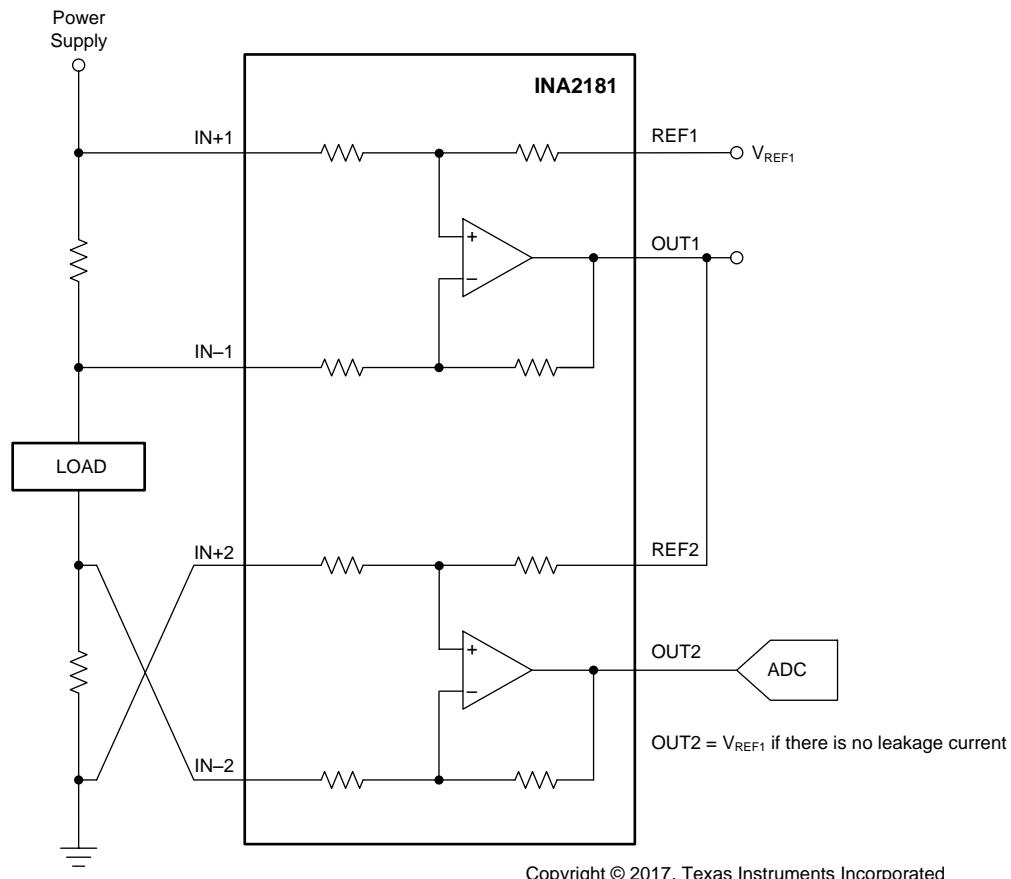


Figure 46. Summing Multiple Currents

The outputs of the INA2181 are easily summed by connecting the output of one channel to the reference input of a second channel. The circuit configuration shown in [Figure 46](#) is an easy way to achieve current summing.

9.2.3 Detecting Leakage Currents



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Figure 47. Detecting Leakage Currents

Occasionally, the need arises to confirm that the current going into a load is identical to the current coming out of a load; usually, as part of diagnostic testing or fault detection. This situation requires precision current differencing, which is the same as summing, except that the two amplifiers have the inputs connected opposite of each other. If the current into a load is equal to the current out of the load, then the voltage at OUT2 is the same as the applied voltage to REF1. To enable accurate differences between the two currents, a reference voltage must be applied. The reference voltage prevents the output of the device from being driven to ground, and also enables detection if the current into the load is either greater than or less than the current coming out of the load.

10 Power Supply Recommendations

The input circuitry of the INAx181 accurately measures beyond the power-supply voltage, V_S . For example, V_S can be 5 V, whereas the bus supply voltage at IN+ and IN- can be as high as 26 V. However, the output voltage range of the OUT pin is limited by the voltages on the VS pin. The INAx181 also withstand the full differential input signal range up to 26 V at the IN+ and IN- input pins, regardless of whether or not the device has power applied at the VS pin.

10.1 Common-Mode Transients Greater Than 26 V

With a small amount of additional circuitry, the INAx181 can be used in circuits subject to transients higher than 26 V, such as automotive applications. Use only Zener diodes or Zener-type transient absorbers (sometimes referred to as *transzorbs*)—any other type of transient absorber has an unacceptable time delay. Start by adding a pair of resistors as a working impedance for the Zener diode; see [Figure 48](#). Keep these resistors as small as possible; most often, around 10 Ω . Larger values can be used with an effect on gain that is discussed in the [Signal Filtering](#) section. This circuit limits only short-term transients; therefore, many applications are satisfied with a 10- Ω resistor along with conventional Zener diodes of the lowest acceptable power rating. This combination uses the least amount of board space. These diodes can be found in packages as small as SOT-523 or SOD-523.

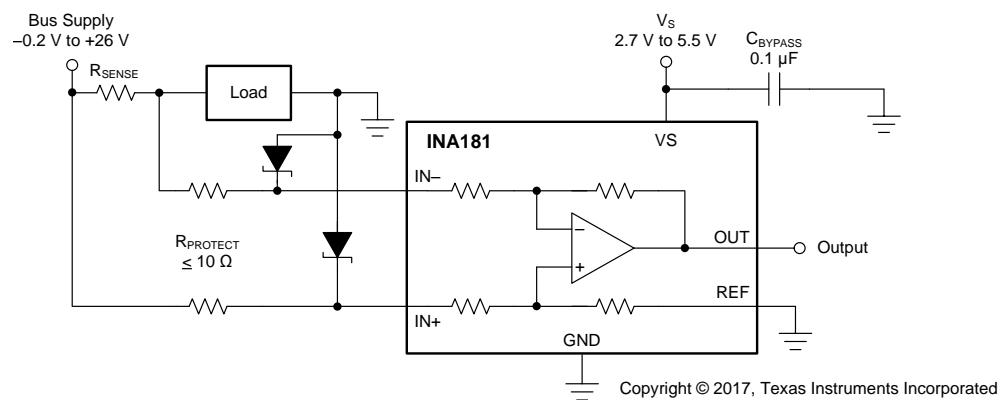


Figure 48. Transient Protection Using Dual Zener Diodes

In the event that low-power Zener diodes do not have sufficient transient absorption capability, a higher-power transzorb must be used. The most package-efficient solution involves using a single transzorb and back-to-back diodes between the device inputs, as shown in [Figure 49](#). The most space-efficient solutions are dual, series-connected diodes in a single SOT-523 or SOD-523 package. In either of the examples shown in [Figure 48](#) and [Figure 49](#), the total board area required by the INAx181 with all protective components is less than that of an SO-8 package, and only slightly greater than that of an MSOP-8 package.

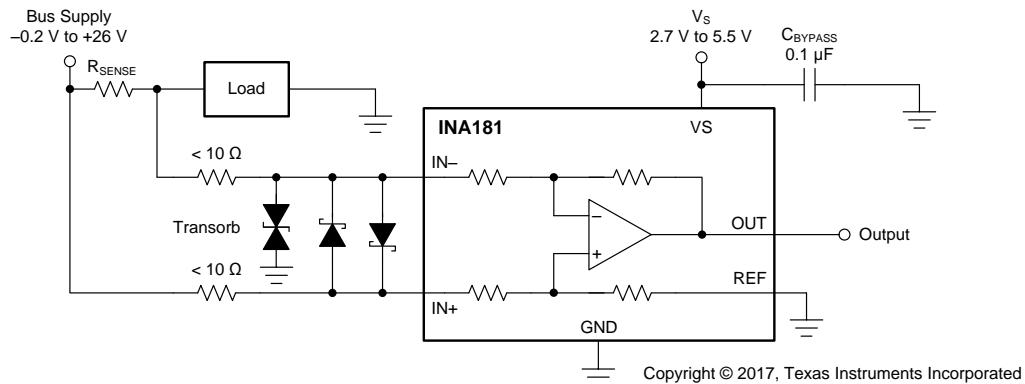


Figure 49. Transient Protection Using a Single Transzorb and Input Clamps

For more information, see [Current Shunt Monitor With Transient Robustness Reference Design](#).

11 Layout

11.1 Layout Guidelines

- Connect the input pins to the sensing resistor using a Kelvin or 4-wire connection. This connection technique makes sure that only the current-sensing resistor impedance is detected between the input pins. Poor routing of the current-sensing resistor commonly results in additional resistance present between the input pins. Given the very low ohmic value of the current resistor, any additional high-current carrying impedance can cause significant measurement errors.
- Place the power-supply bypass capacitor as close as possible to the device power supply and ground pins. The recommended value of this bypass capacitor is 0.1 μ F. Additional decoupling capacitance can be added to compensate for noisy or high-impedance power supplies.

11.2 Layout Example

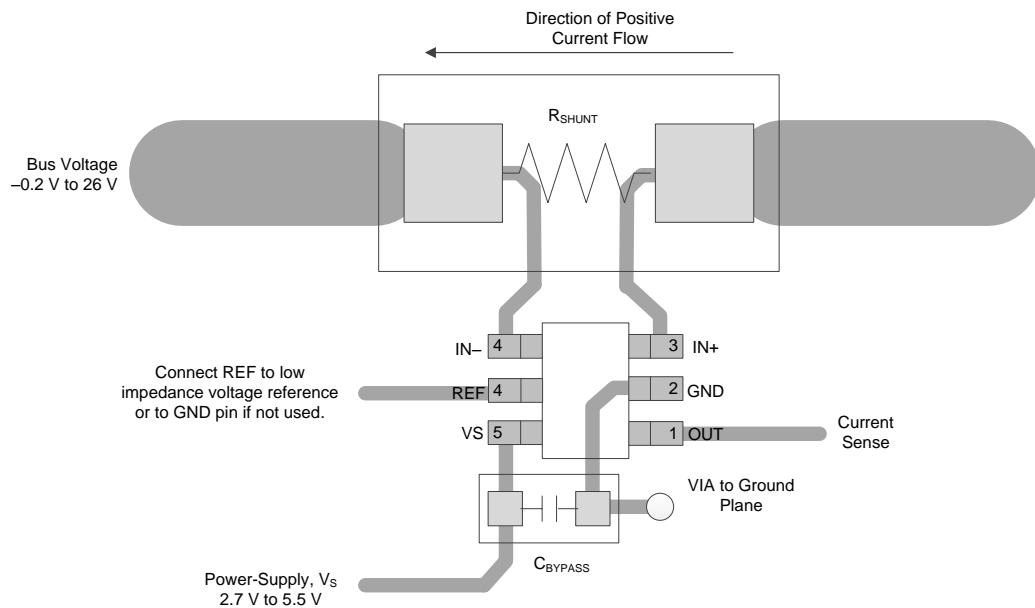


Figure 50. Single-Channel Recommended Layout

Layout Example (continued)

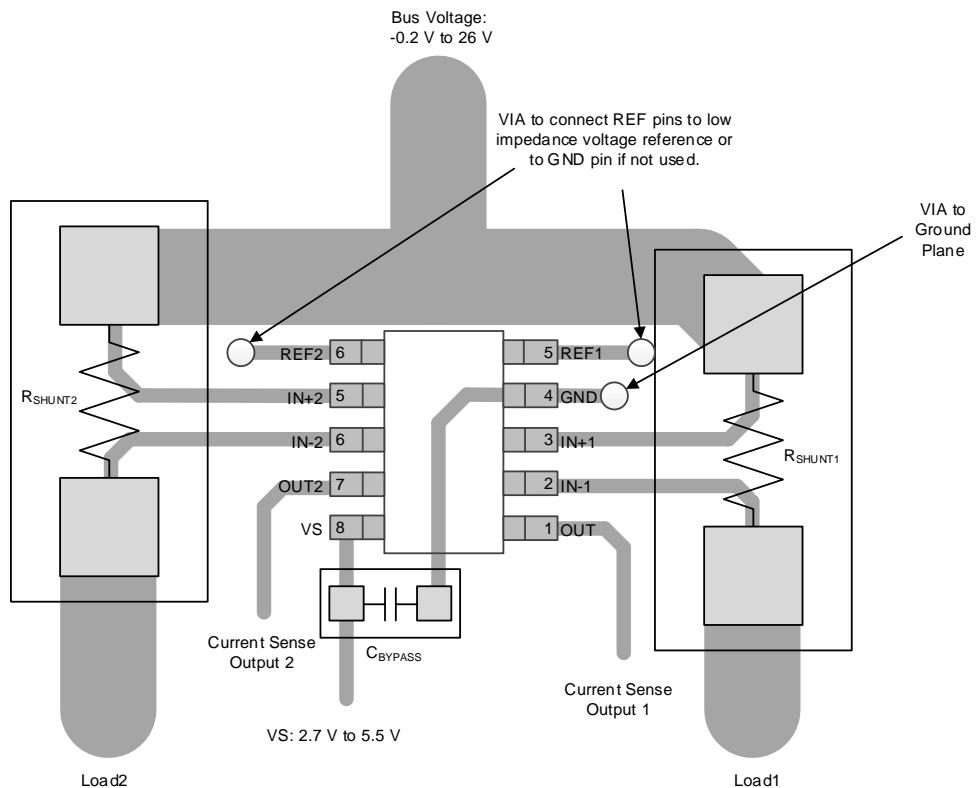


Figure 51. Dual-Channel Recommended Layout

Layout Example (continued)

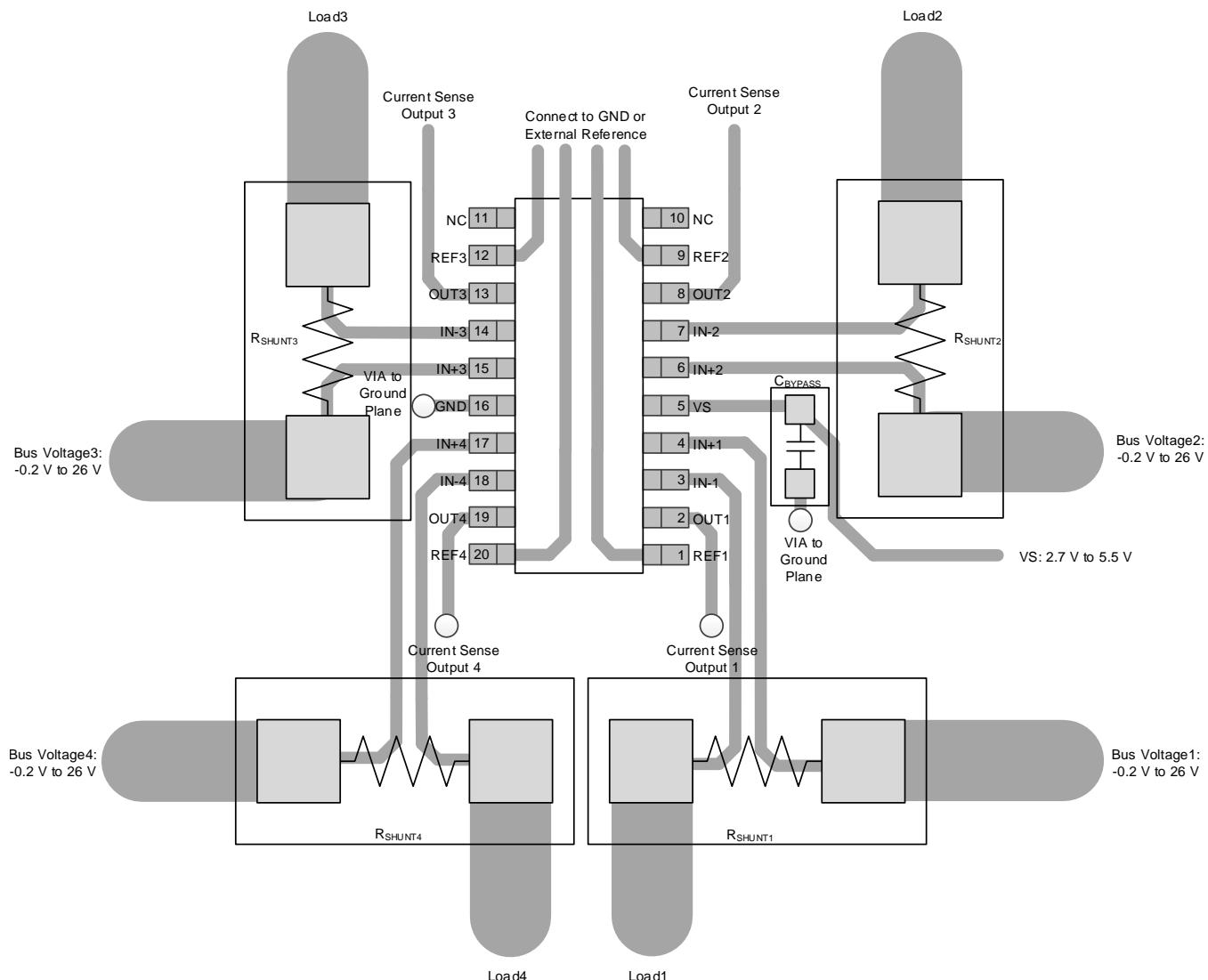


Figure 52. Quad-Channel Recommended Layout

12 Device and Documentation Support

12.1 Device Support

12.1.1 Development Support

Current Shunt Monitor With Transient Robustness Reference Design

12.2 Documentation Support

12.2.1 Related Documentation

For related documentation see the following:

- [INA180-181EVM User's Guide](#)
- [INA2180-2181EVM User's Guide](#)
- [INA4180-4181EVM User's Guide](#)

12.3 Related Links

Table 4 lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 4. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
INA181	Click here				
INA2181	Click here				
INA4181	Click here				

12.4 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.5 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community **TI's Engineer-to-Engineer (E2E) Community.** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support **TI's Design Support** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.6 Trademarks

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

12.7 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

 ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

12.8 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
INA181A1IDBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	18JD	Samples
INA181A1IDBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	18JD	Samples
INA181A2IDBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	1AED	Samples
INA181A2IDBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	1AED	Samples
INA181A3IDBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	1AFD	Samples
INA181A3IDBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	1AFD	Samples
INA181A4IDBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	1AGD	Samples
INA181A4IDBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	1AGD	Samples
INA2181A1IDGSR	PREVIEW	VSSOP	DGS	10	2500	TBD	Call TI	Call TI	-40 to 125		
INA2181A1IDGST	PREVIEW	VSSOP	DGS	10	250	TBD	Call TI	Call TI	-40 to 125		
INA2181A2IDGSR	PREVIEW	VSSOP	DGS	10	2500	TBD	Call TI	Call TI	-40 to 125		
INA2181A2IDGST	PREVIEW	VSSOP	DGS	10	250	TBD	Call TI	Call TI	-40 to 125		
INA2181A3IDGSR	PREVIEW	VSSOP	DGS	10	2500	TBD	Call TI	Call TI	-40 to 125		
INA2181A3IDGST	PREVIEW	VSSOP	DGS	10	250	TBD	Call TI	Call TI	-40 to 125		
INA2181A4IDGSR	PREVIEW	VSSOP	DGS	10	2500	TBD	Call TI	Call TI	-40 to 125		
INA2181A4IDGST	PREVIEW	VSSOP	DGS	10	250	TBD	Call TI	Call TI	-40 to 125		
INA4181A1IPWR	PREVIEW	TSSOP	PW	20	2000	TBD	Call TI	Call TI	-40 to 125		
INA4181A1IPWT	PREVIEW	TSSOP	PW	20	250	TBD	Call TI	Call TI	-40 to 125		
INA4181A2IPWR	PREVIEW	TSSOP	PW	20	2000	TBD	Call TI	Call TI	-40 to 125		
INA4181A2IPWT	PREVIEW	TSSOP	PW	20	250	TBD	Call TI	Call TI	-40 to 125		
INA4181A3IPWR	PREVIEW	TSSOP	PW	20	2000	TBD	Call TI	Call TI	-40 to 125		
INA4181A3IPWT	PREVIEW	TSSOP	PW	20	250	TBD	Call TI	Call TI	-40 to 125		
INA4181A4IPWR	PREVIEW	TSSOP	PW	20	2000	TBD	Call TI	Call TI	-40 to 125		
INA4181A4IPWT	PREVIEW	TSSOP	PW	20	250	TBD	Call TI	Call TI	-40 to 125		

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
PINA2181A1IDGSR	ACTIVE	VSSOP	DGS	10	2500	TBD	Call TI	Call TI	-40 to 125		Samples
PINA2181A2IDGSR	ACTIVE	VSSOP	DGS	10	2500	TBD	Call TI	Call TI	-40 to 125		Samples
PINA2181A3IDGSR	ACTIVE	VSSOP	DGS	10	2500	TBD	Call TI	Call TI	-40 to 125		Samples
PINA2181A4IDGSR	ACTIVE	VSSOP	DGS	10	2500	TBD	Call TI	Call TI	-40 to 125		Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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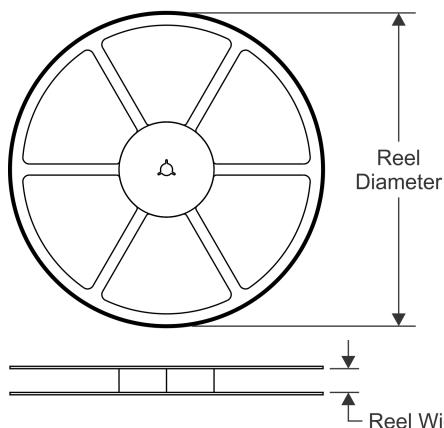
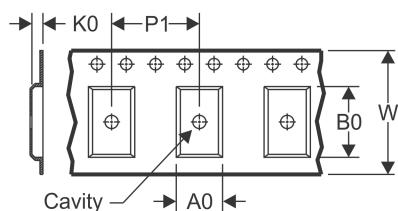
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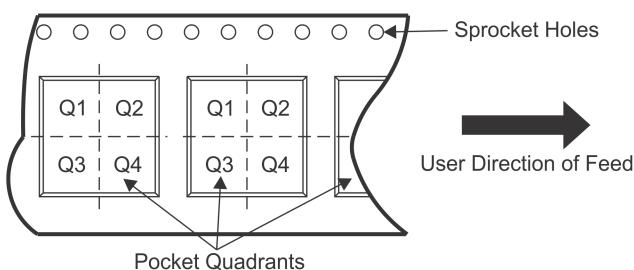
www.ti.com

PACKAGE OPTION ADDENDUM

14-Nov-2017

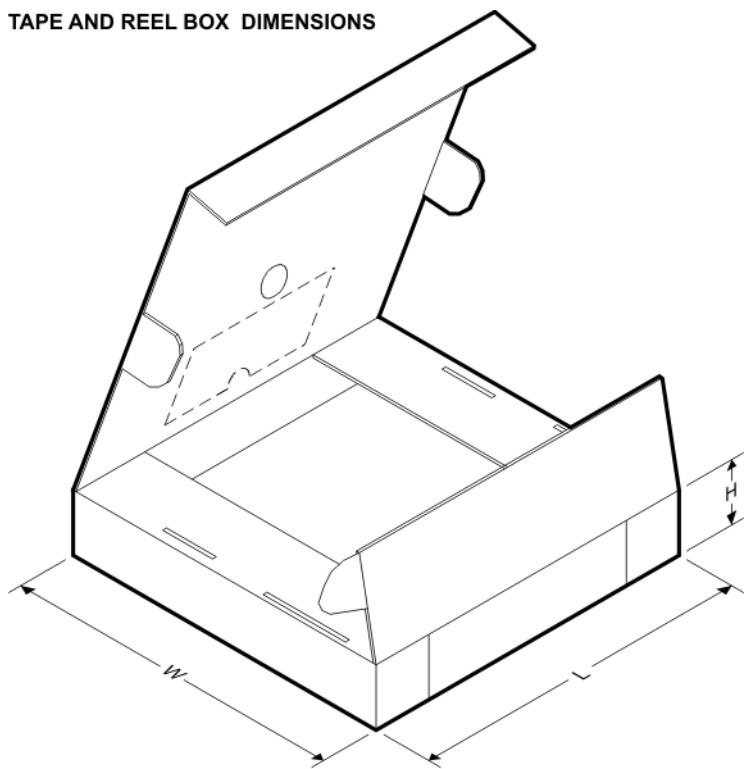
TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA181A1IDBVR	SOT-23	DBV	6	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
INA181A1IDBVT	SOT-23	DBV	6	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
INA181A2IDBVR	SOT-23	DBV	6	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
INA181A2IDBVT	SOT-23	DBV	6	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
INA181A3IDBVR	SOT-23	DBV	6	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
INA181A3IDBVT	SOT-23	DBV	6	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
INA181A4IDBVR	SOT-23	DBV	6	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
INA181A4IDBVT	SOT-23	DBV	6	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3

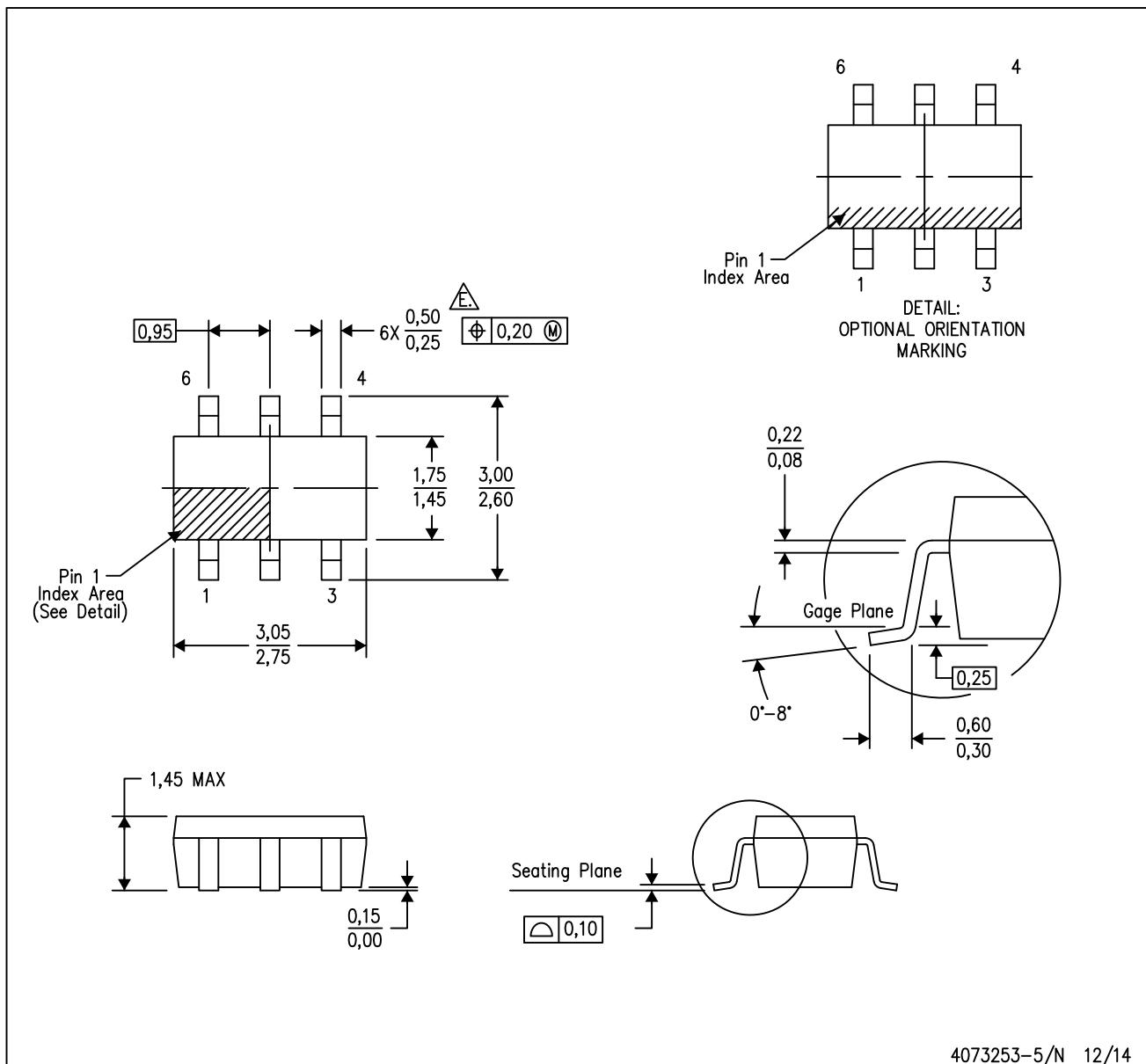
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
INA181A1IDBVR	SOT-23	DBV	6	3000	180.0	180.0	18.0
INA181A1IDBVT	SOT-23	DBV	6	250	180.0	180.0	18.0
INA181A2IDBVR	SOT-23	DBV	6	3000	180.0	180.0	18.0
INA181A2IDBVT	SOT-23	DBV	6	250	180.0	180.0	18.0
INA181A3IDBVR	SOT-23	DBV	6	3000	180.0	180.0	18.0
INA181A3IDBVT	SOT-23	DBV	6	250	180.0	180.0	18.0
INA181A4IDBVR	SOT-23	DBV	6	3000	180.0	180.0	18.0
INA181A4IDBVT	SOT-23	DBV	6	250	180.0	180.0	18.0

DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



4073253-5/N 12/14

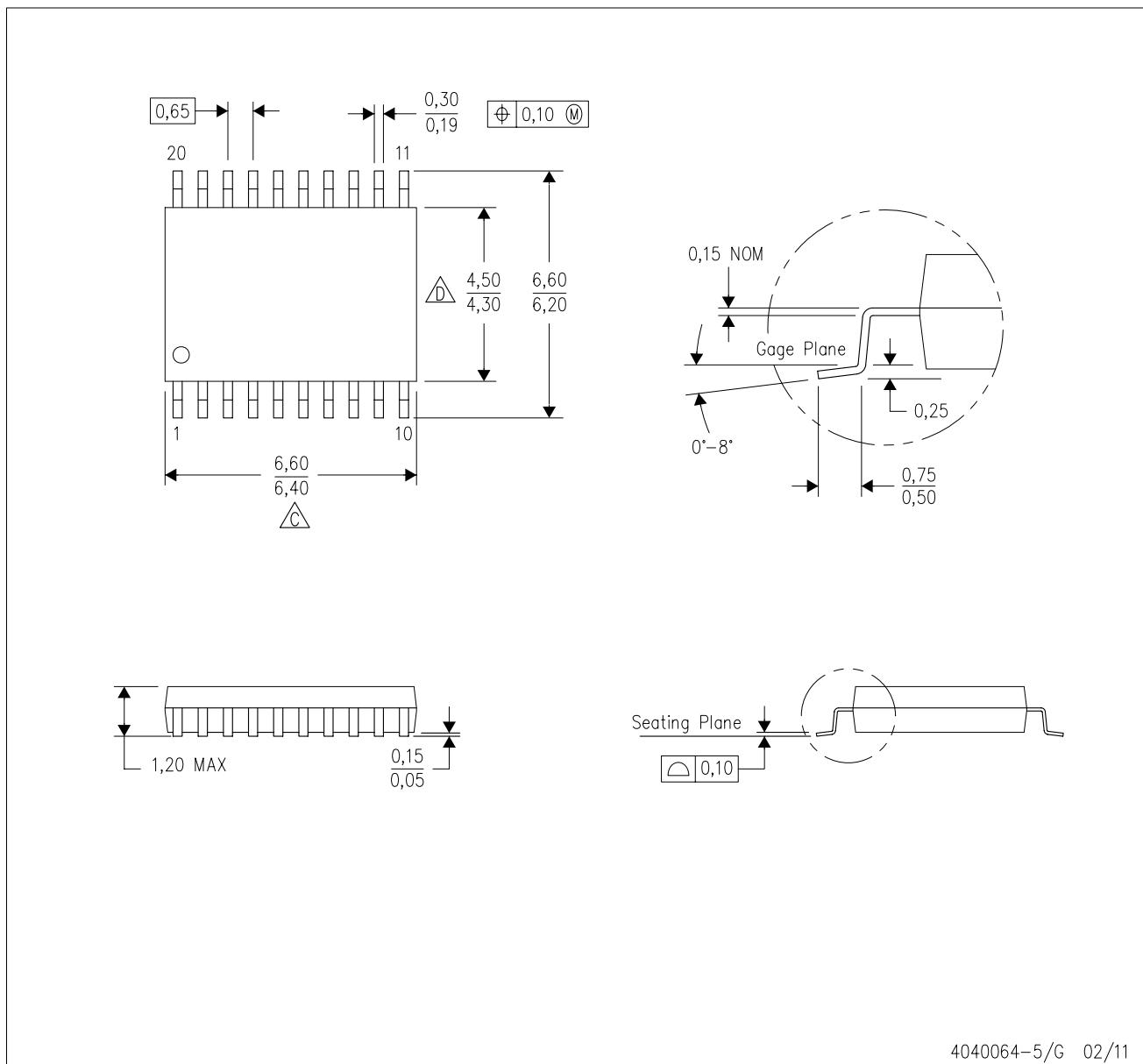
NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.

△ Falls within JEDEC MO-178 Variation AB, except minimum lead width.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

 C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

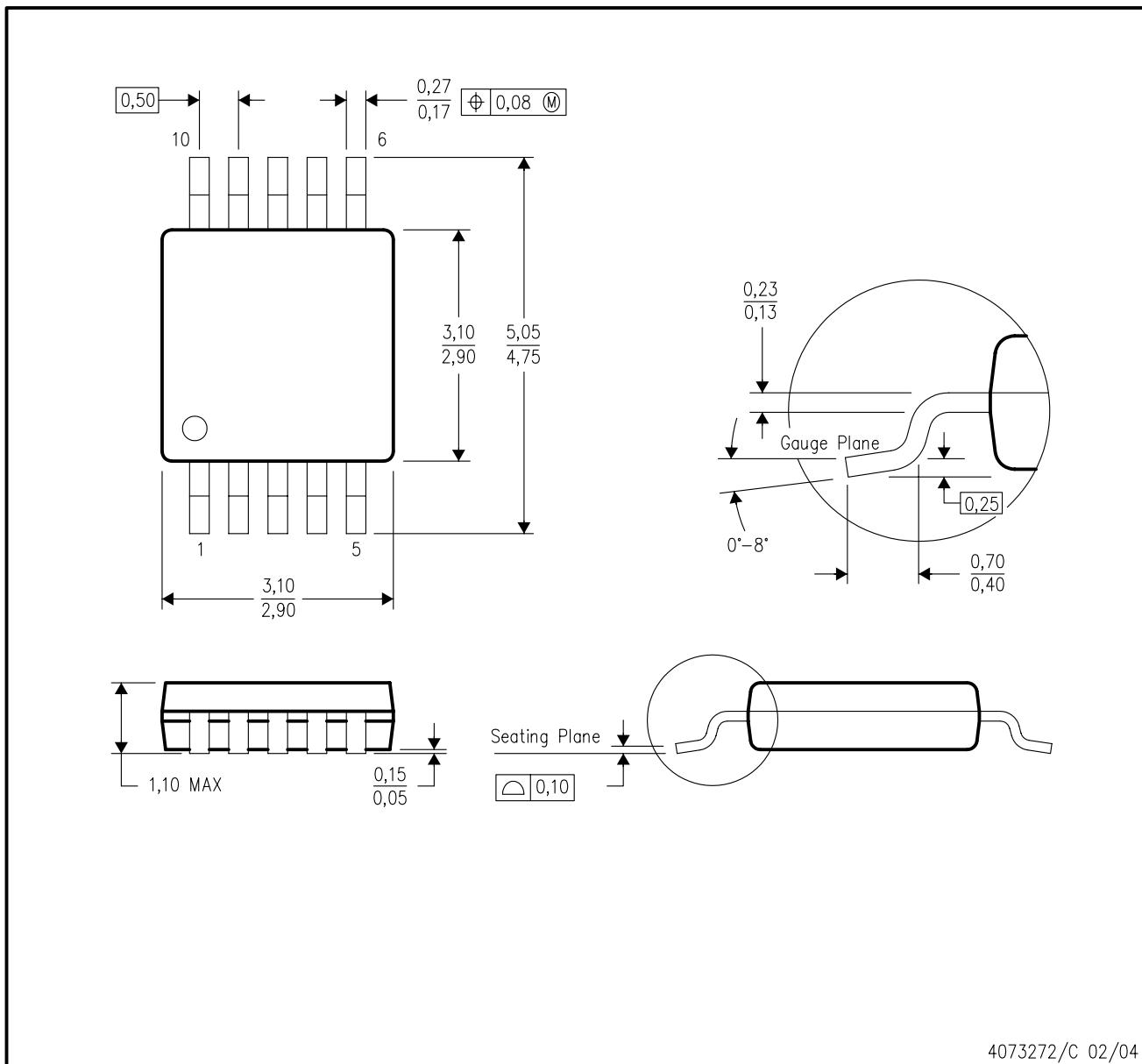
 D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153

4040064-5/G 02/11

DGS (S-PDSO-G10)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-187 variation BA.

4073272/C 02/04

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